

Report from WG2:
Common Characterisation and Physics Issues

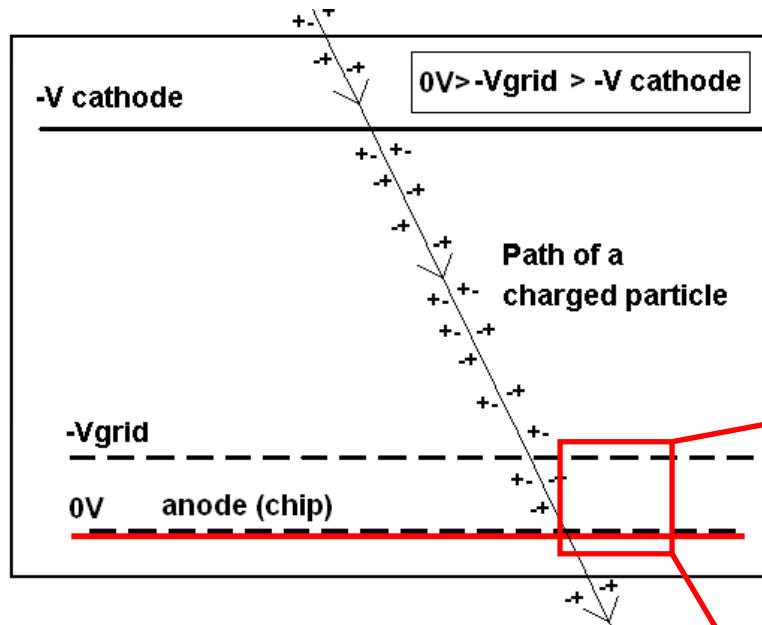
Harry van der Graaf
2nd RD-51 Workshop, Paris, Oct 15, 2008

Discharge protection for MPGDs

Martin Fransen, Nikhef

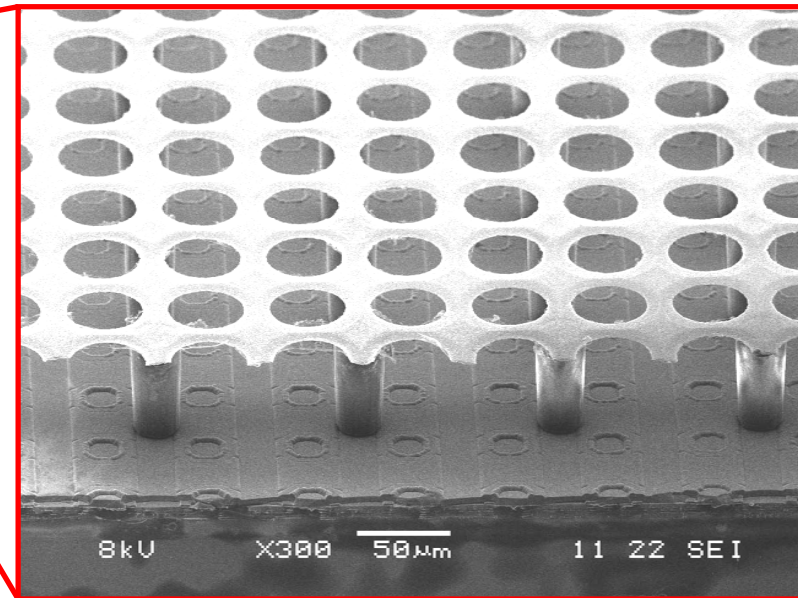


Gridpix detectors

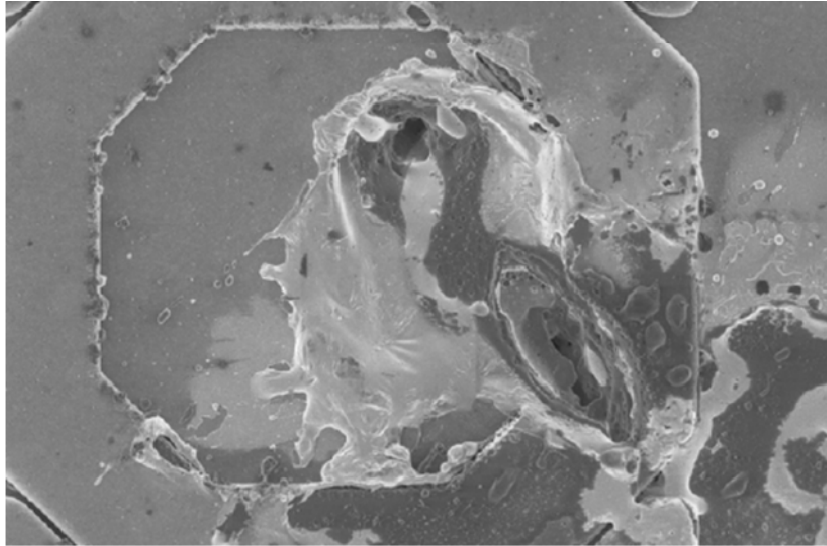


- Grid made by lithographic procedure. (University of Twente)

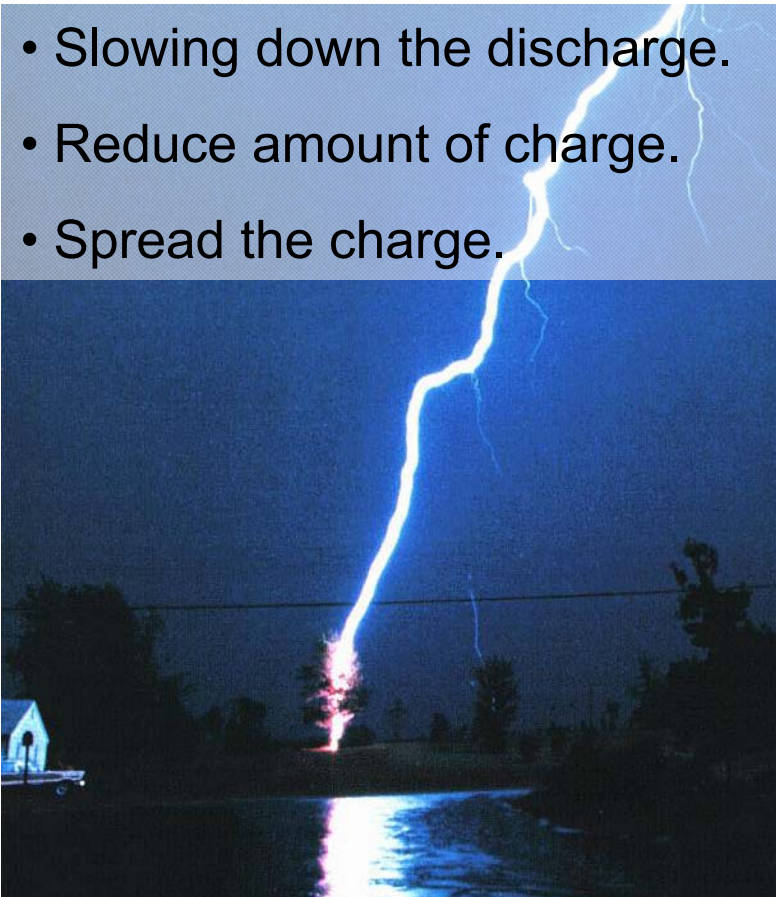
- Drift volume (1mm-1m).
- Grid.
- Gain region.
- Pixel readout chip.



Gridpix detectors



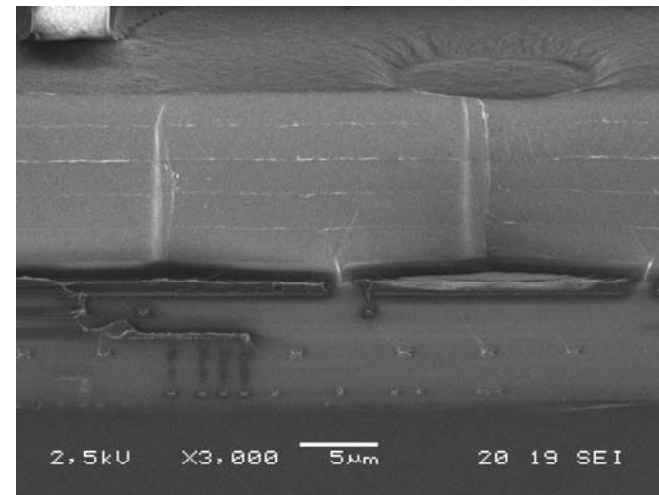
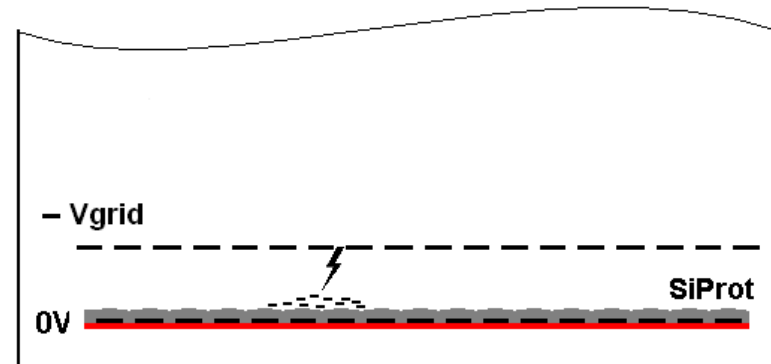
- Drift volume $E = \sim 0.1-1 \text{ kV/cm}$.
- Grid.
- Gain region $E = \sim 80 \text{ kV/cm}$
- Timepix chip.



- Slowing down the discharge.
- Reduce amount of charge.
- Spread the charge.

High resistive coating

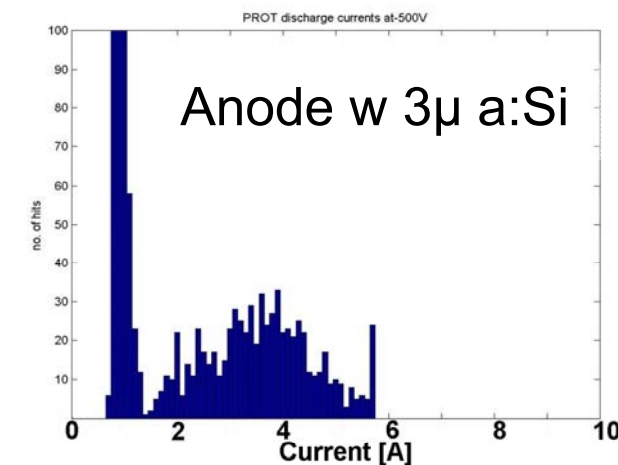
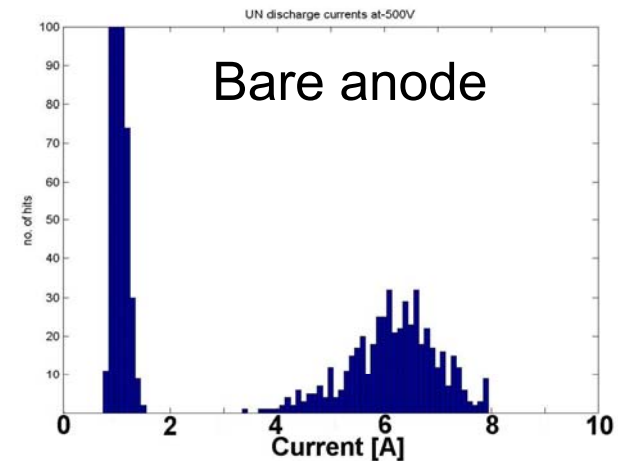
- Deposit on the chip without killing the electronics.
- Quenching of discharges.
- Some conductivity to prevent net charge build up.
- Amorphous silicon (IMT Neuchatel), SiProt.
- Si_3N_4 , silicon nitride (Twente), SiNProt.
- Provoke discharges with α radiation to test the layer.



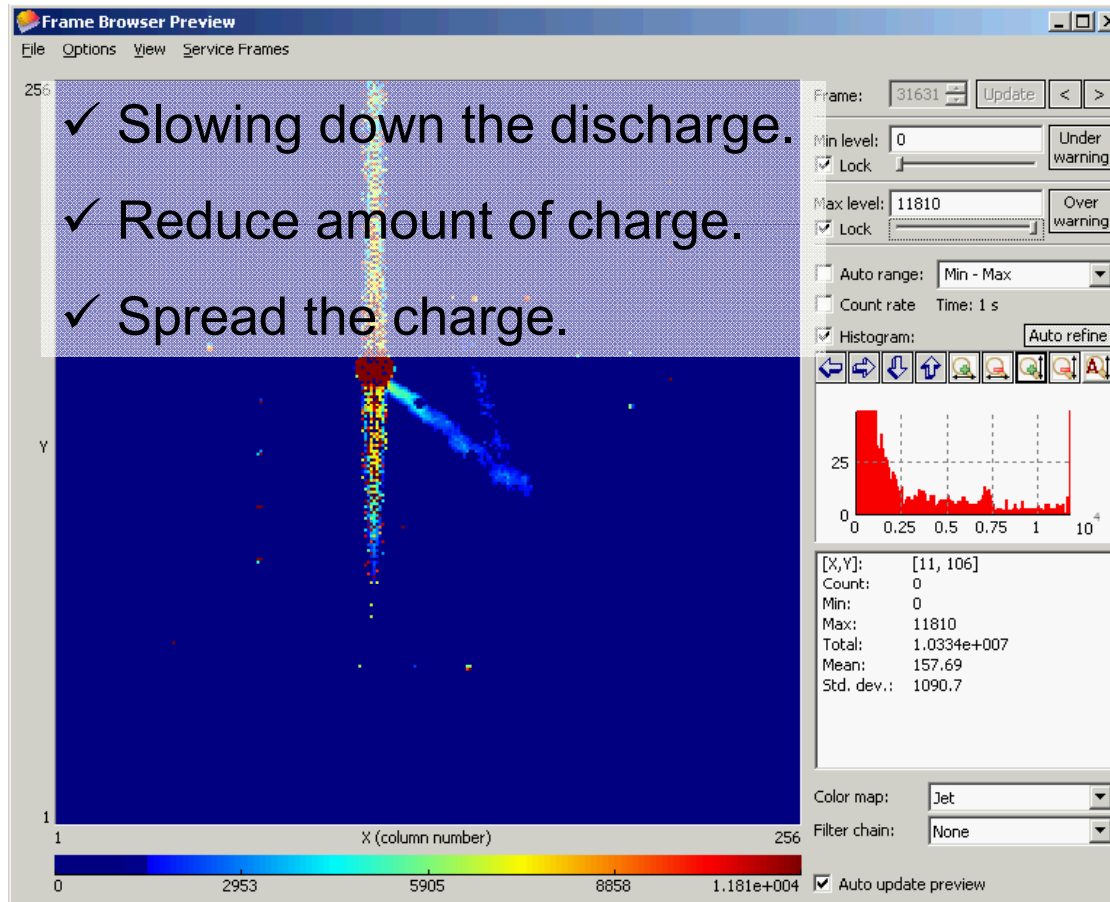
Discharge quenching

- 3 μm a-Si.
- Dummy anodes.
- Peak currents:
 - 6-7 amps on bare anode.
 - 3-4 amps on prot. anode.

- Reduced heat dissipation.



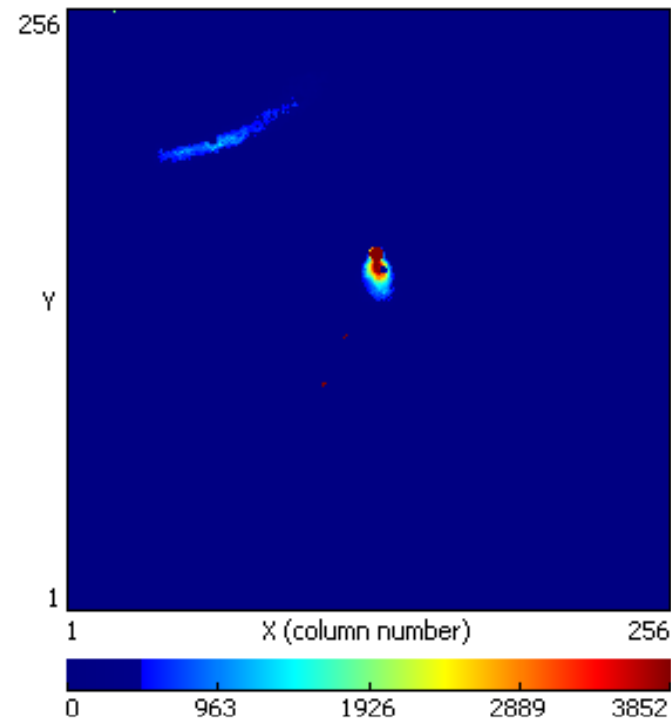
Discharge quenching



Pixelman software: IEAP, Prague

Recent developments

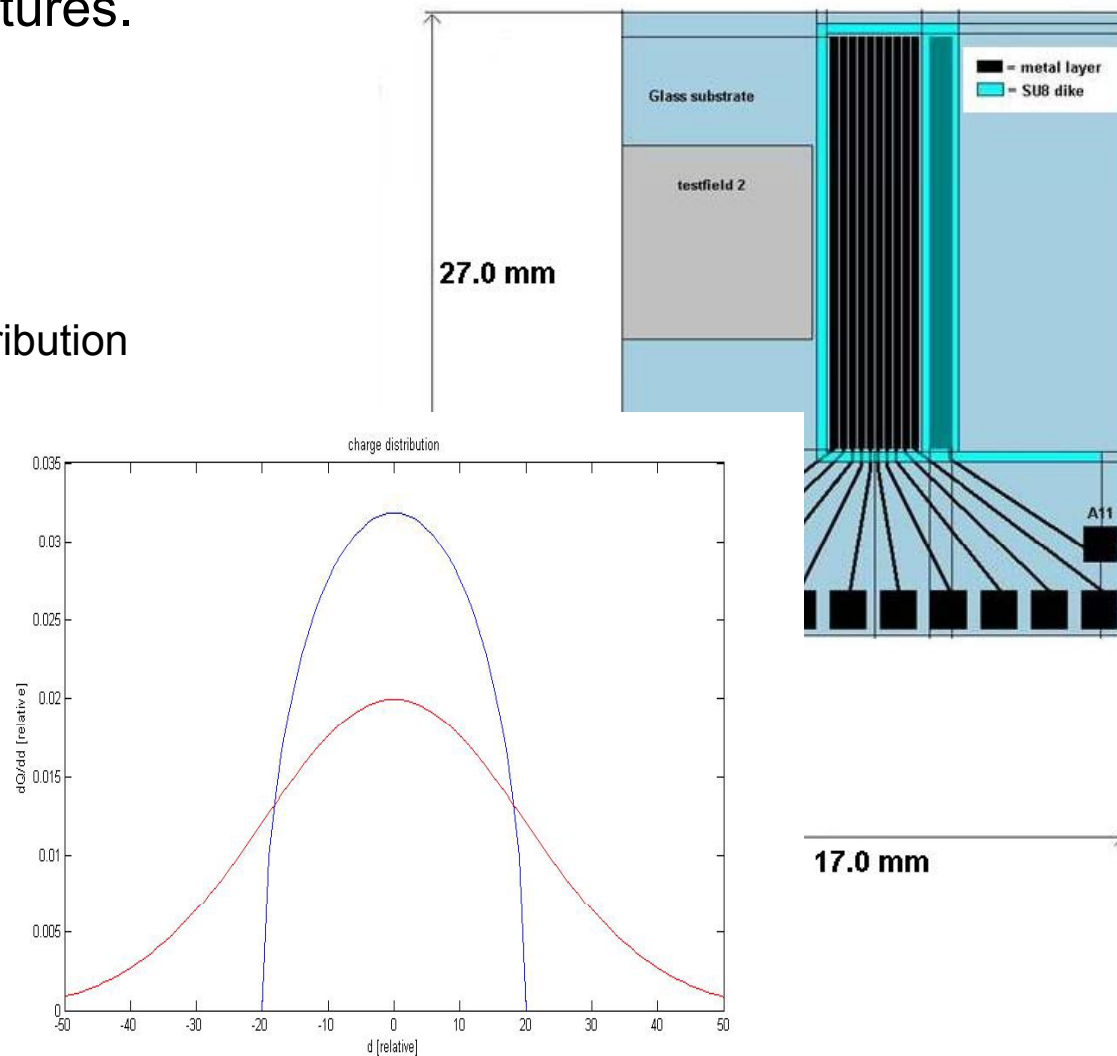
- Charge per pixel reduced to \sim pC \rightarrow
- Medipix 3 with input protection.
- chip with 7 μ SiNProt still alive after >10 days.
- At Twente both Ingrid and SiNProt can be applied! \rightarrow post processing faster and cheaper.



Discharge on a SiNProt covered Timepix chip.

Discharge test structure

- Foolproof test structures.
- To quantify:
 - Time of discharge
 - Amount of charge
 - charge density distribution
- As function of:
 - SiProt thickness
 - Gas mixture
 - Voltage





MPGD ageing

Fred Hartjes
NIKHEF

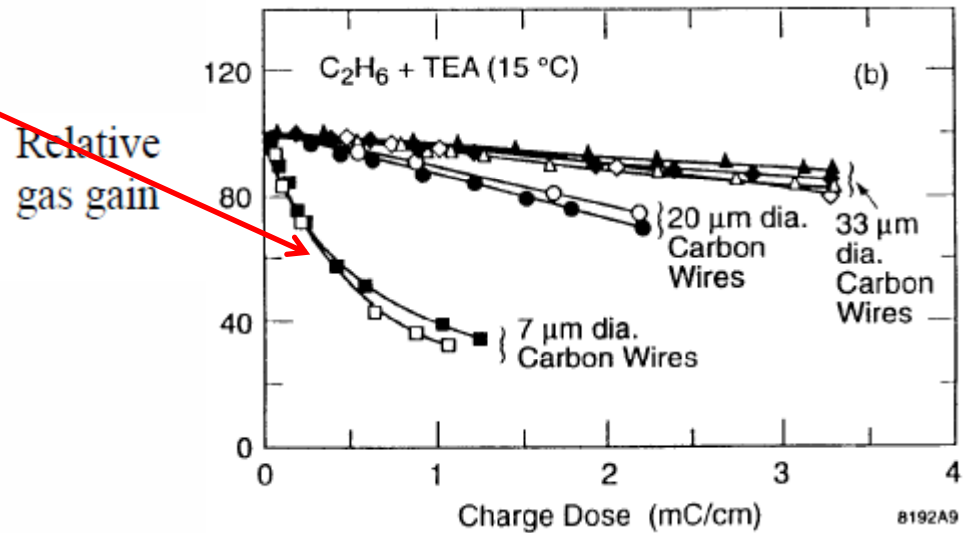


Magic or **science?**

2nd RD51 collaboration meeting
Paris, October 13 - 15, 2008

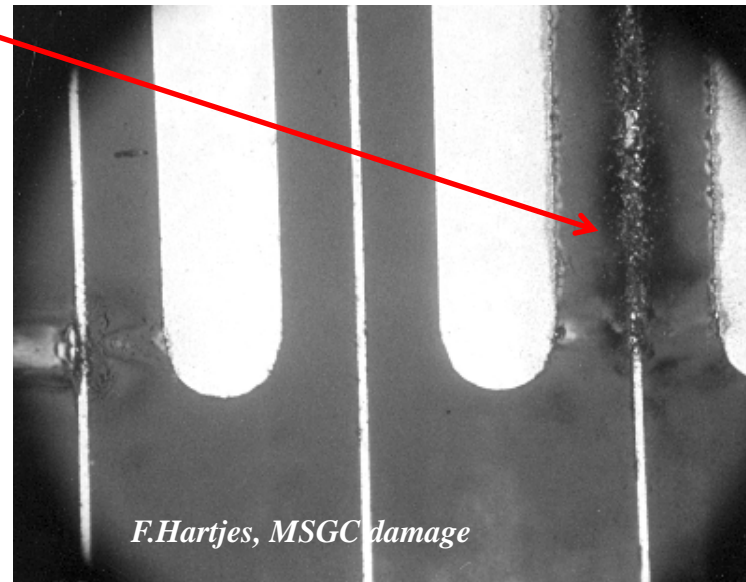
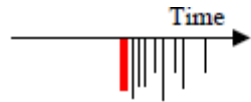
detector?

- Loss of avalanche gain
 - Rapid or slower



J. Va'vra, NIM A387(1997)183

- Broadening amplitude spectrum
 - => More variation gain



F.Hartjes, MSGC damage

- Increased

Loss of gain in gaseous detectors

- Figure of merit: accumulated **charge** on the anode surface

– Kadyk (I. Juricic, J.A. Kadyk, Proceedings Workshop on Radiation Damage to Wire Chambers, Berkeley 1986, p. 141)

$$R = \frac{1}{Q} * \frac{\Delta A}{A}$$

where

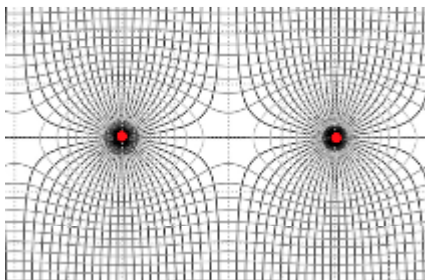
- Q is the accumulated charge per cm anode (wires or strips) or cm² (MPGD, PPC,)
 - G is the gas gain
 - D is the dose (particles per cm resp cm²)
 - n_e is the primary ionisation per hit
- Define the ageing rate R (%/C/cm) or (%/C/cm²) as

Competition: ageing of silicon sensors

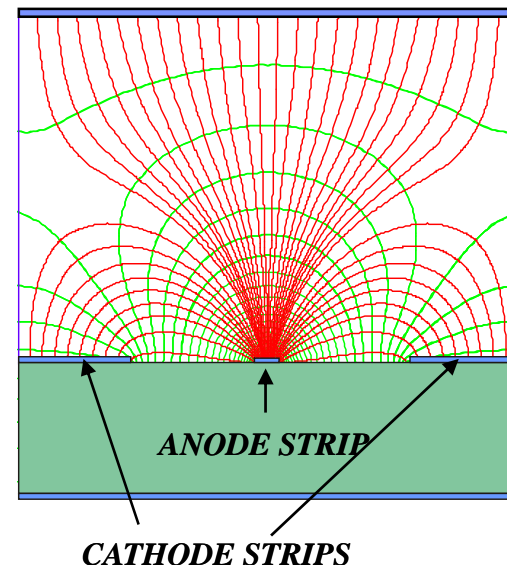
- Figure of merit: n_{eq} **dose**
 - Damage from applied radiation converted into damage from radiation caused by 1 MeV neutrons
 - => easy evaluation of radiation hardness
 - Often using neutrons from nuclear plant for ageing characterisation
- Nature of silicon sensor damage

gaseous detectors

Wire chamber: $1/R$
amplification field



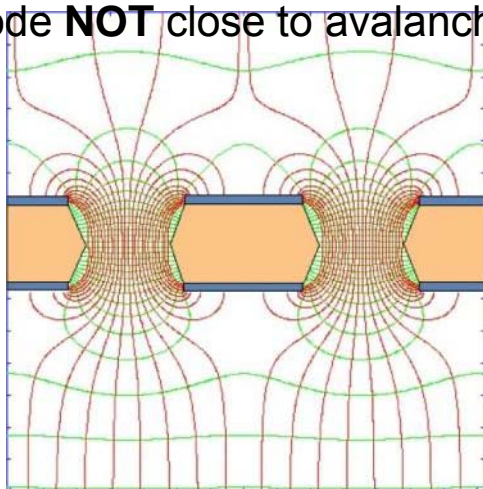
MSGC: dipole
amplification field
Very high field at
cathode edge



A.Oed, Nucl. Instr. and Meth. A263(1988)351

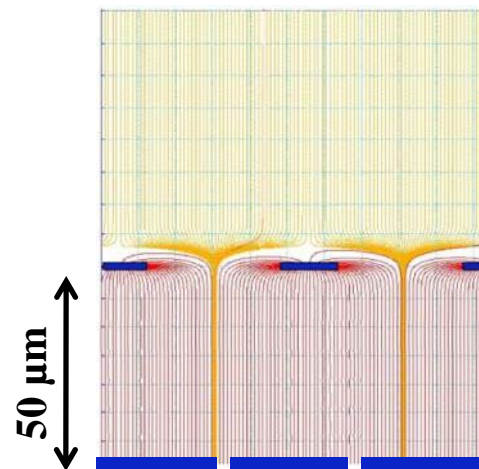
GEM: amplification field across \sim
 $25 \mu\text{m}$ (high at the edges of the
hole)

Anode **NOT** close to avalanche



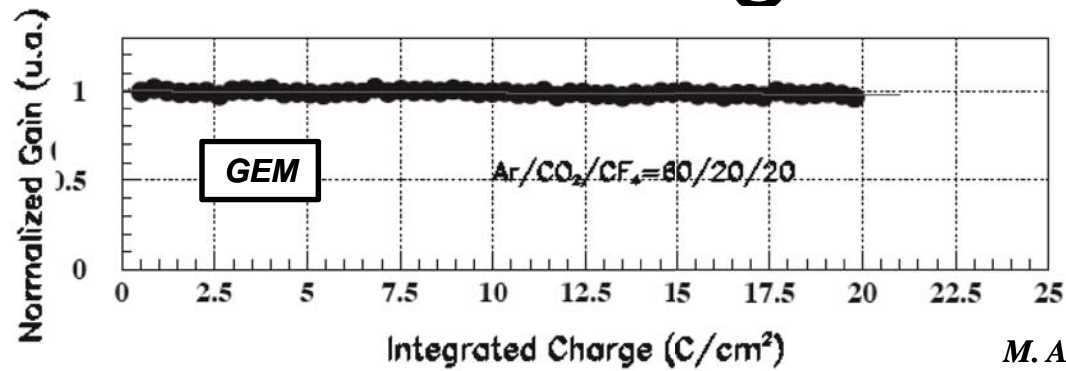
F. Sauli, Nucl. Instr. and Methods A386(1997)531

Micromegas: homogeneous
amplification field across 50



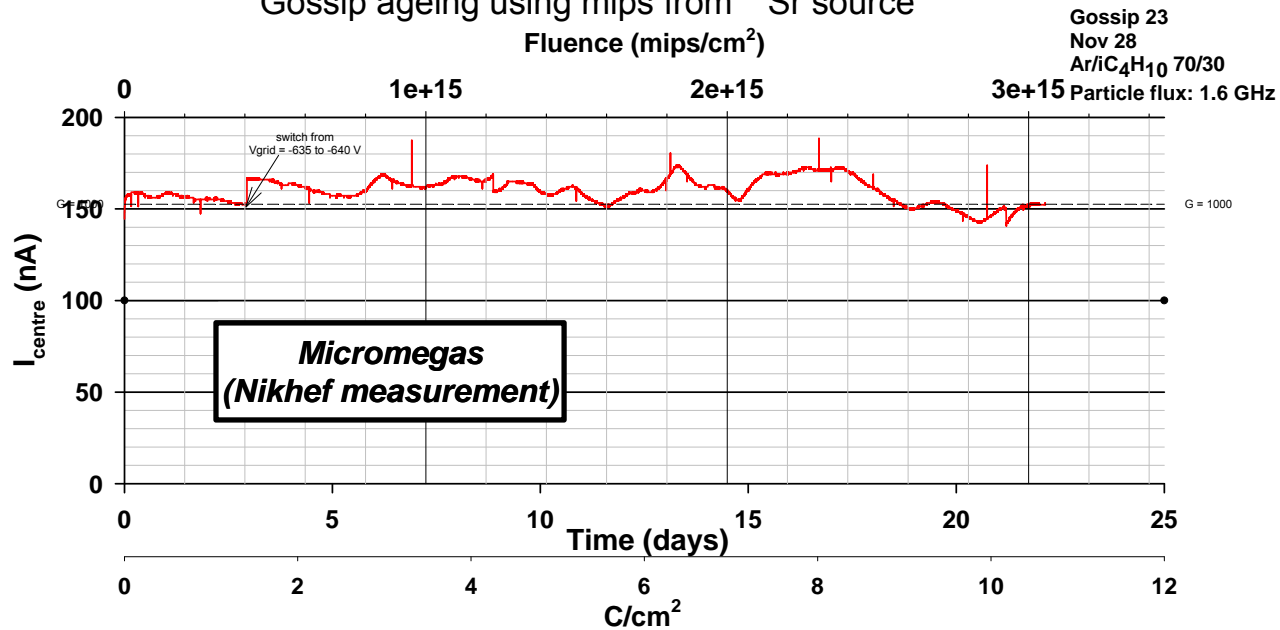
Y. Giomataris et al, Nucl. Instr. and Meth. A376(1996)239

Micromegas



*M. Alfonsi et al,
Nucl. Instr. and Meth. A518(2004)106*

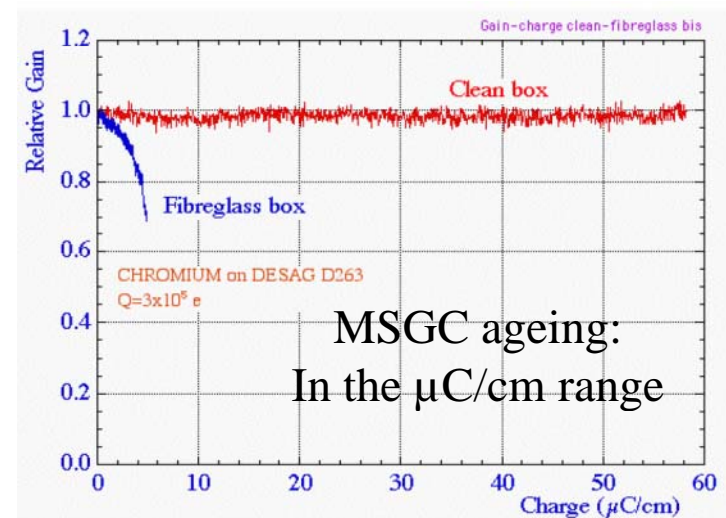
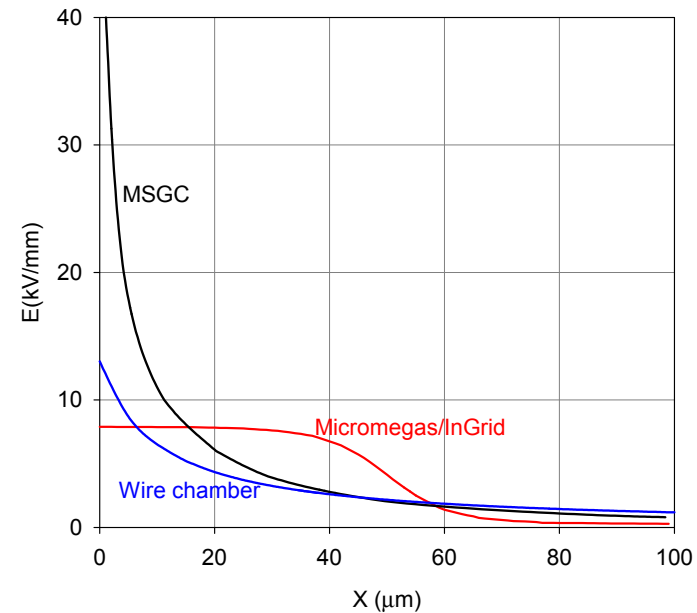
Gossip ageing using mips from ⁹⁰Sr source
Fluence (mips/cm²)



technology

- Polymerisation will be mainly at the end of the avalanche where the electron density is highest
 - A few μm away from the anode
 - Exception: GEM
- Key issue
 - What is the field at the anode surface?
 - High field \Rightarrow high avalanche temperature

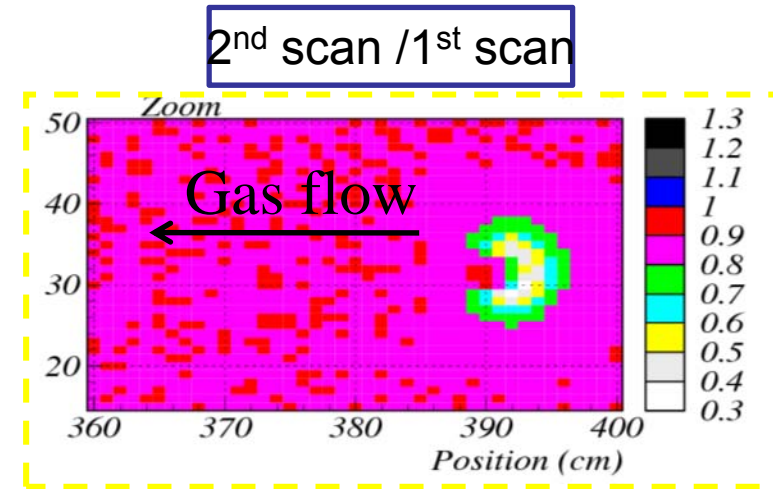
Field strength (E) along the central drift path (X) to the anode for three different electrode geometries



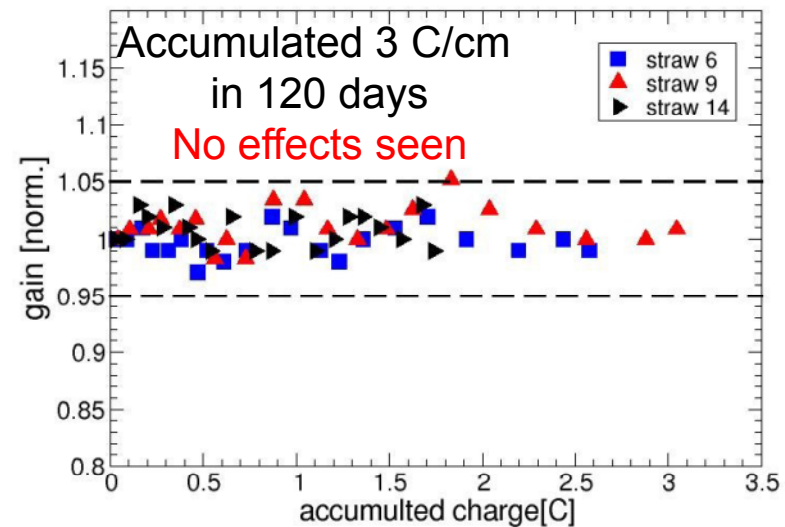
MSGC ageing:
In the $\mu\text{C}/\text{cm}$ range

Result

- At accumulated charge **2.8 mC/cm** (peak value)



- ◆ Strong unexpected ageing effect
 - ◆ No ageing downstream



Design recommendations

- Reduce field on cathode surface as much as possible
- Use the cleanest materials you can afford (NASA and CERN database)
 - But there's no need getting bankrupt
- Add filter at the in coming gas close to the detector (molecular sieve 5A)
- Consider adding special ageing chamber for advance cleaning (see LHCB experience)
- **But** don't expect this to be absolutely safe to prevent ageing
- Do as much ageing prototype tests as you can on as much different conditions to get an impression of the robustness of your detector
 - Different particles
 - Different irradiation rates
 - Different sites

Operational recommendations

- While running, monitor the chamber performance on a daily basis and take immediate action when observing ageing phenomena
- Don't change from gas supplier while running an experiment
- Be prepared to apply additives
 - CF_4 + oxygen containing molecule like CO_2 or alcohols
 - Water (active moisture control and monitoring), don't let it pass the 1% limit
 - **=> But be aware that these measures might worsen the situation in your specific case**

some thoughts on charging-up effects

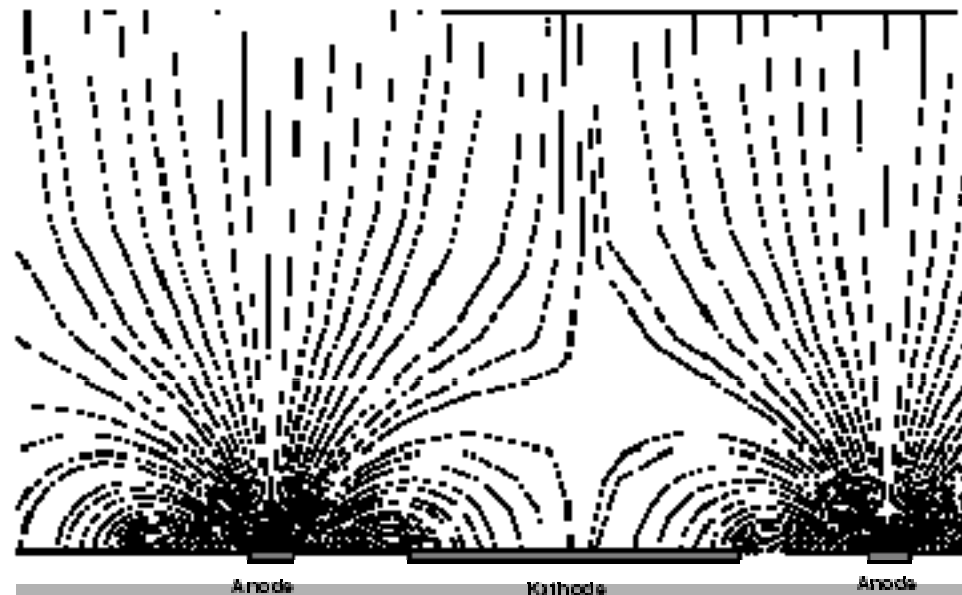
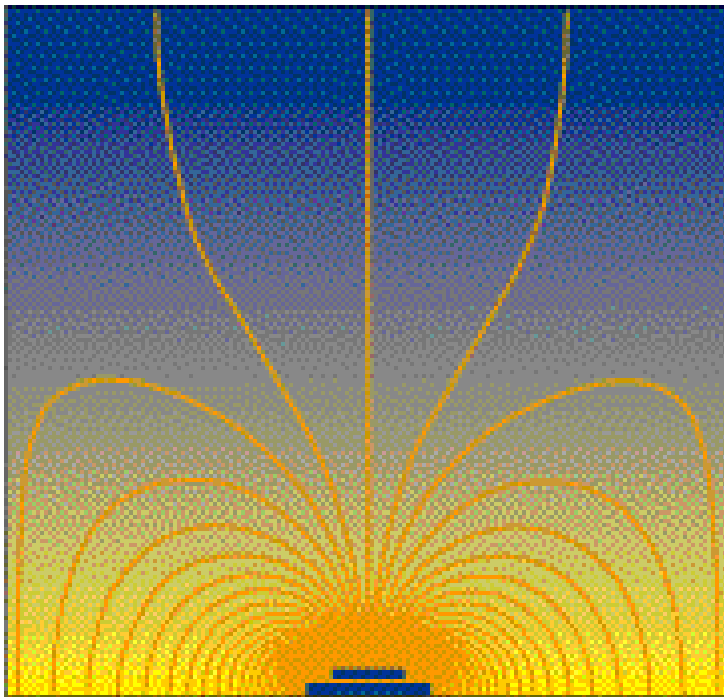
HvdG, Nikhef

RD51 Workshop, Paris, 2008

Micro Strip Gas Counters: hard to operate:

- discharges, ruining electrodes
- ageing

! Very strong electric field in insulator's volume & surface !



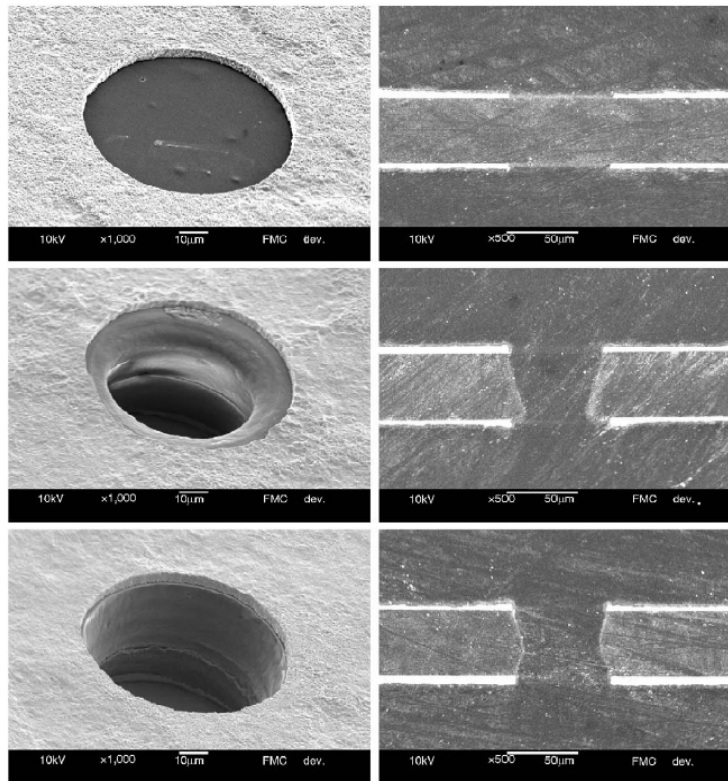
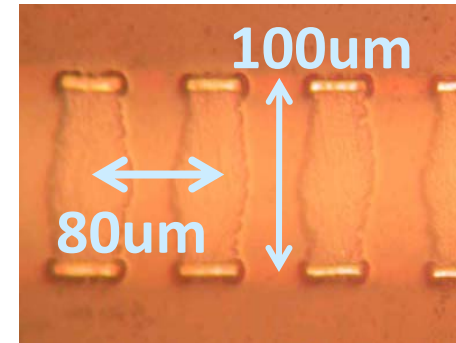
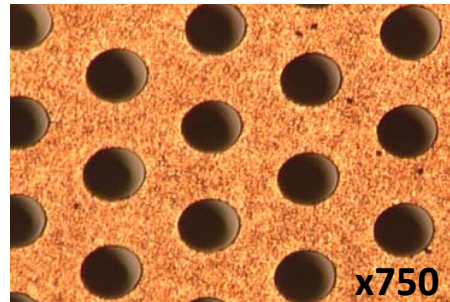
GEM Production

RIKEN/SciEnergy GEM
(thick-foil and fine-pitch)

pitch 80um

hole 40um

thickness 100um



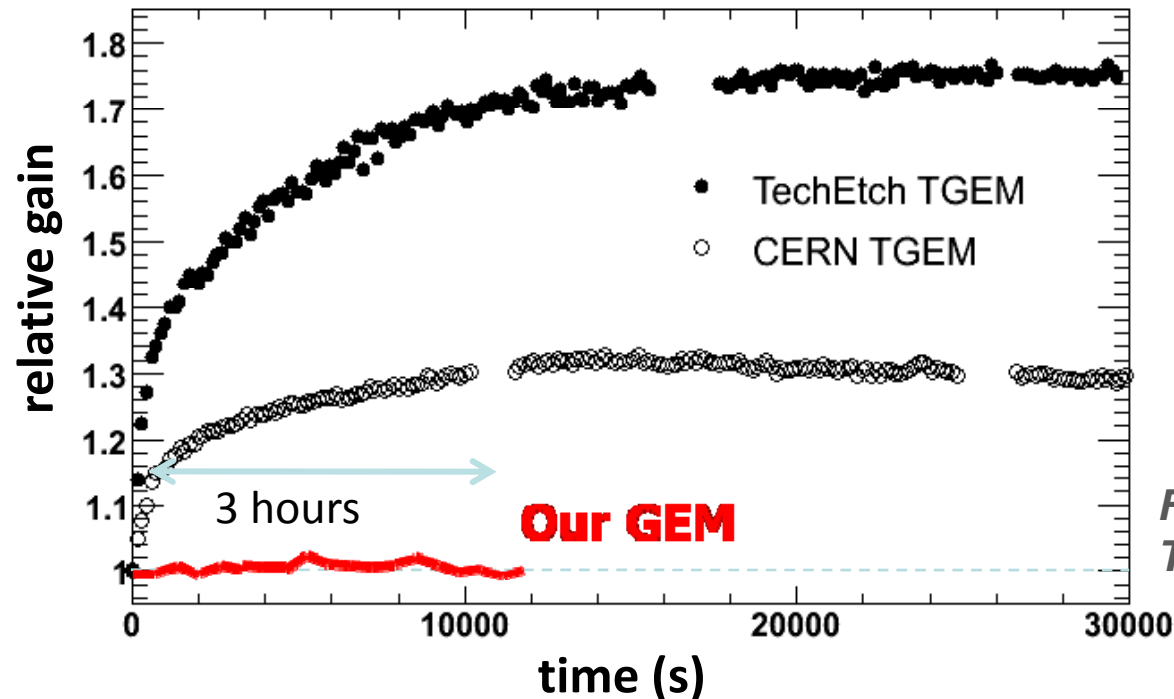
Remove copper
by wet etching

Irradiate CO₂ laser

Remove remaining edge
from the other side

Gain instability (RIKEN GEM)

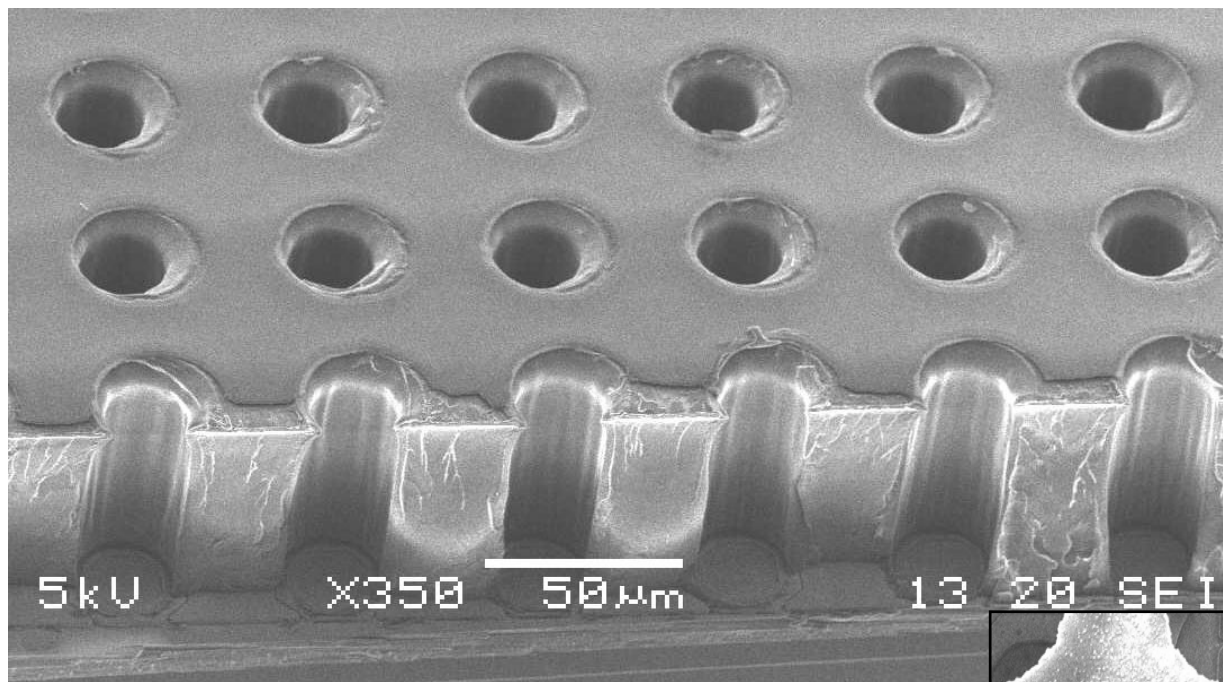
No increase and decrease just after HV on.



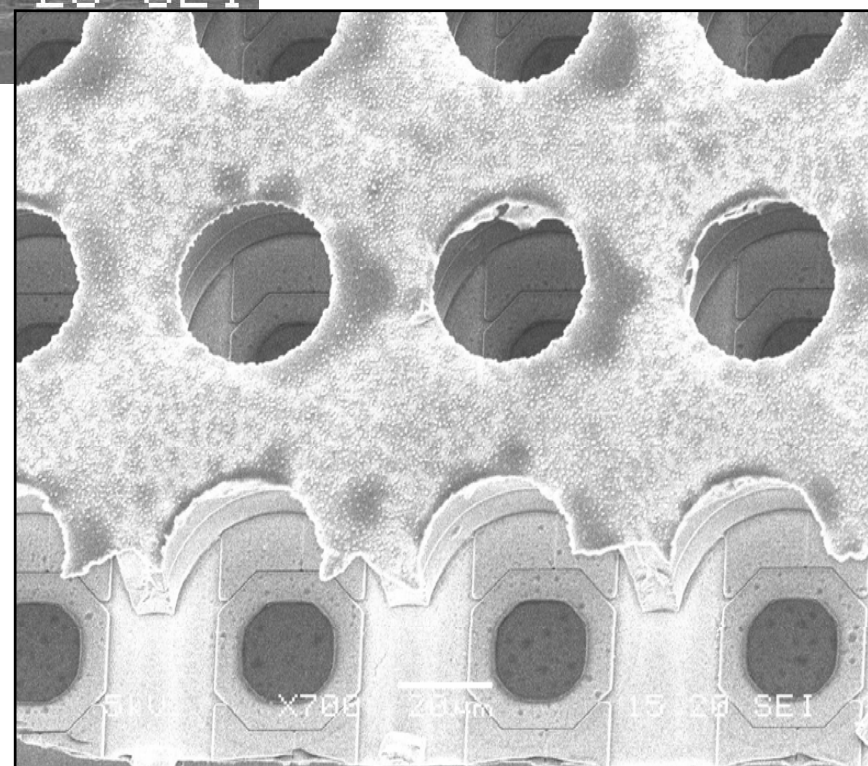
F. Simon (IEEE, 2006)

T. Tamagawa(IEEE,2007)

- No gain increase in short measurements
- This is not for a special batch of GEMs but for all GEMs we produced
- Possible reasons;
 - ✓ Less charging-up due to cylindrical hole shape
 - ✓ Less polarization of Liquid Crystal Polymer



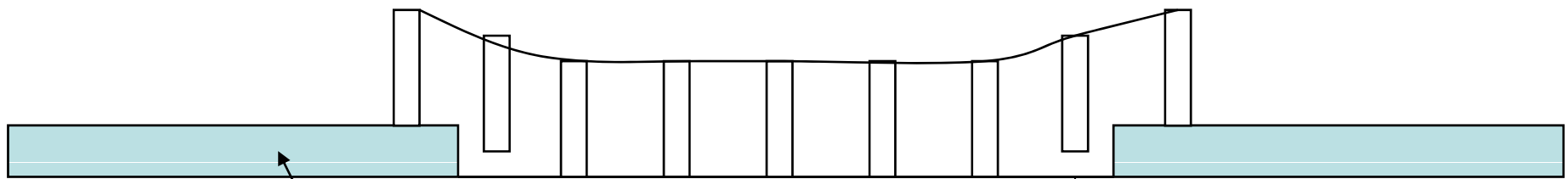
GemGrid 1



GemGrid 2

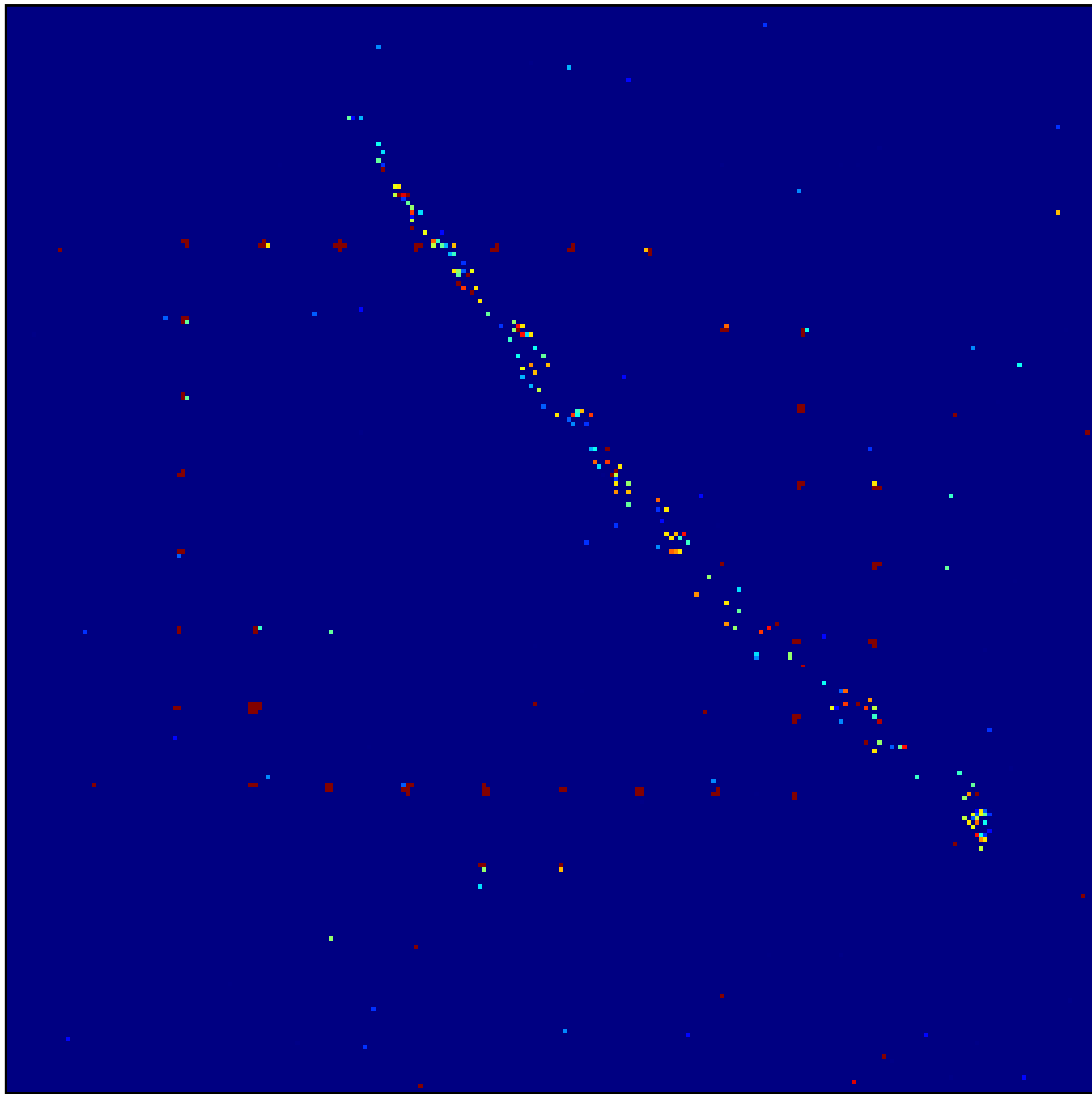
conductivity of kapton

Micromegas on pillars



Edge discharge protection foil

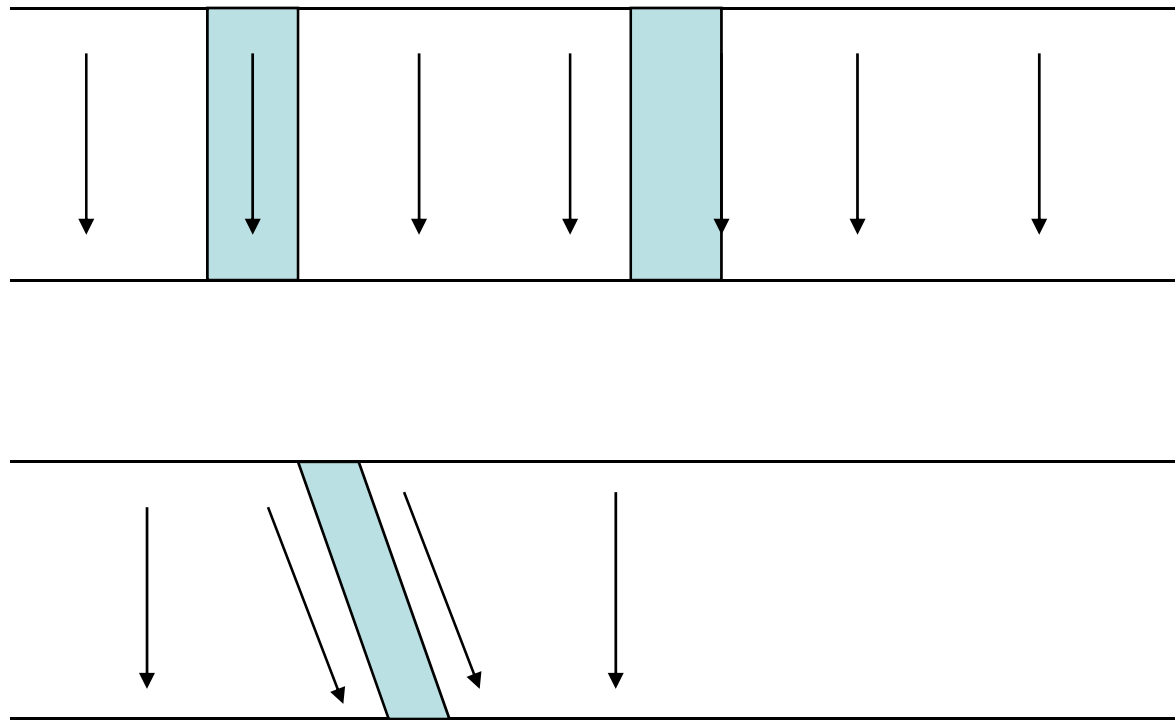
discharges + vibrations



Charge-up effects

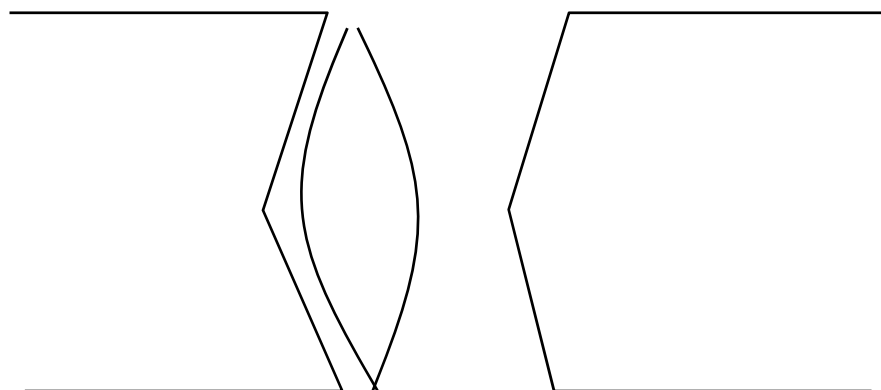
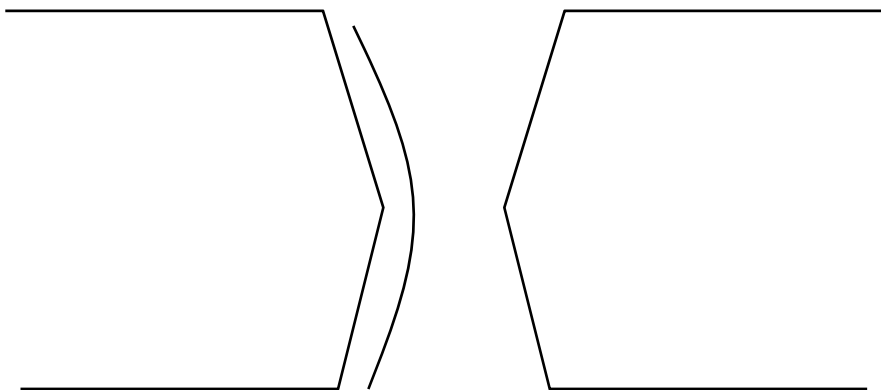
After (rapid) ramping of HV:

- polarisation: reduction of E-field in insulator (bulk) volume
In homogeneous field with insulator // to field: nothing

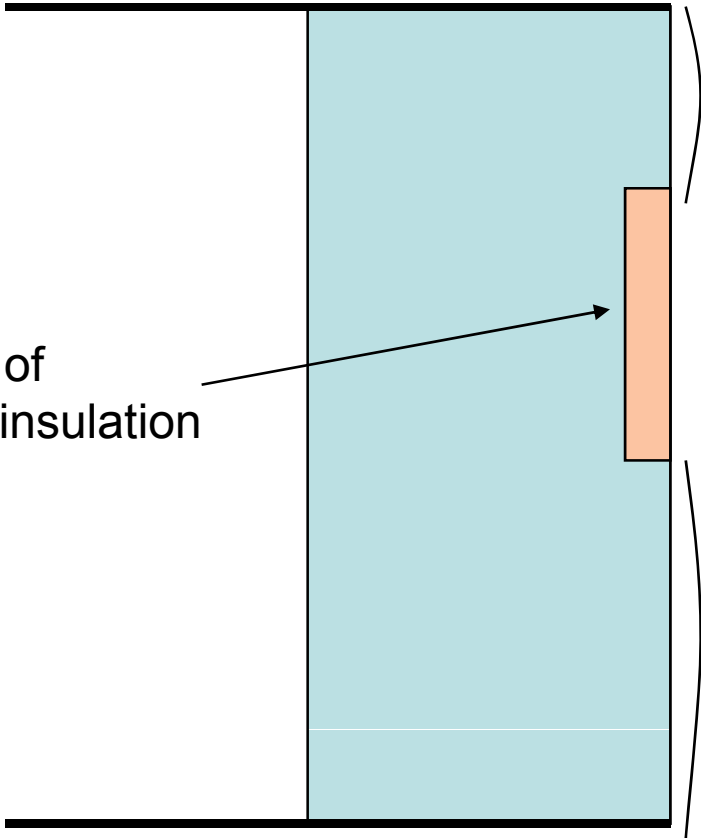


With E component perp. on insulating surface: modification of potential by hitting e- and/or ions until E // surface

GEM hole



region of
worse insulation



equalizing with water

Stronger effects for
good insulator

Very preliminary:

Use as little as possible insulating surfaces // strong E fields

Even more preliminary:

As for gain: GEMs perform less than (corresponding) Micromegas

Plans for
**MPGD Radiation hardness
tests for full detectors and
components**

Matteo Alfonsi, **Gabriele Croci**, Elena Rocco,
Serge Duarte Pinto, Leszek Ropelewski

CERN GDD Group

2nd RD51 Collaboration Meeting

Paris 13-15 October 2008

Working Group 2

Outline

- Full Detector Tests
 - Standard Triple GEM
 - Bulk MicroMegas
 - THGEM
- Components Tests
 - Standard Triple GEM components
 - Electrical Tests
 - Mechanical Tests

Method followed for Full Detectors

- Make a series of measurement before putting this detector in beam of ^{60}Co photons
- We would like to know if the performance of the detector is changed after strong irradiation (Total integrated dose of 10^6 - 10^7 Gy)

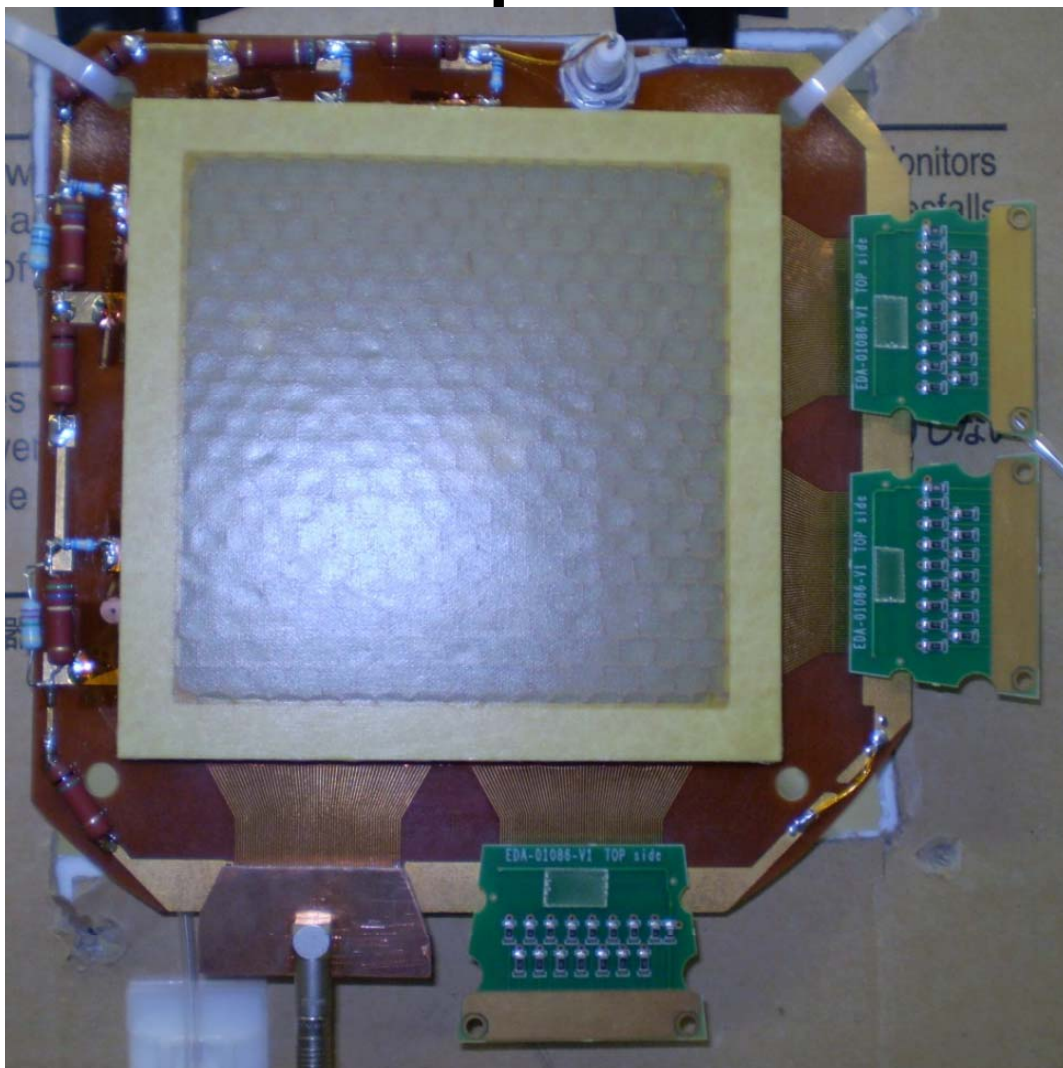
List of measurements

- Gain
- Rate Capability
- Discharge Probability
- Time Charging up Scan Type 1: Power on the detector and start to irradiate at the same time
- Time Charging up Scan Type 2: Power on the detector before starting the irradiation
- 2D Test (for Triple GEM)
- Test of uniformity over active area
- Counting plateau

What might happen after strong irradiation..

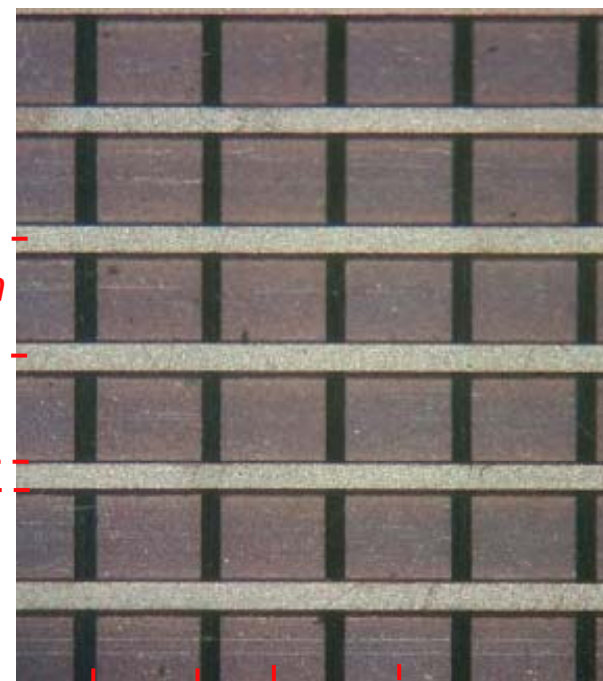
- Gain → For TGEM, if the kapton resistivity is changed we can have less gain than before at the same voltage; it may happen that this variation may only be on the irradiated spots.
- Gain variation with time → The detector can have different charging up properties
-

The Triple GEM Detector used

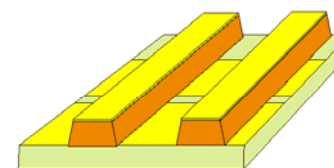


10 x 10 cm² Active Area

Gas Mixture used Ar/CO₂ 70%/30%



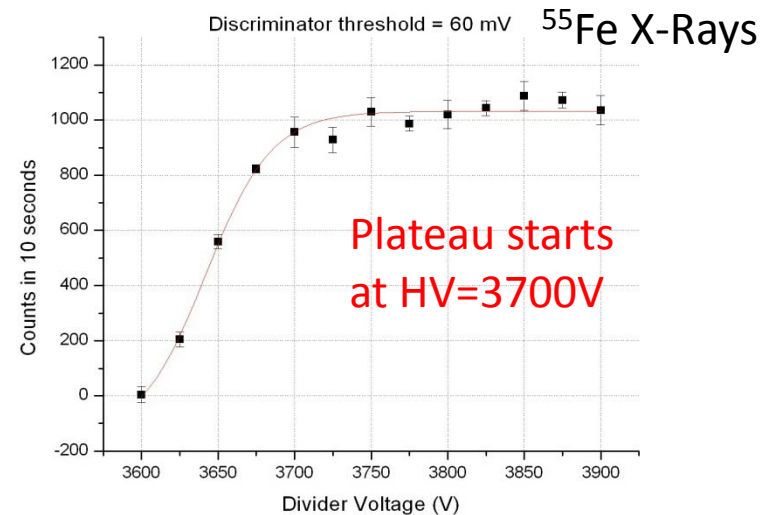
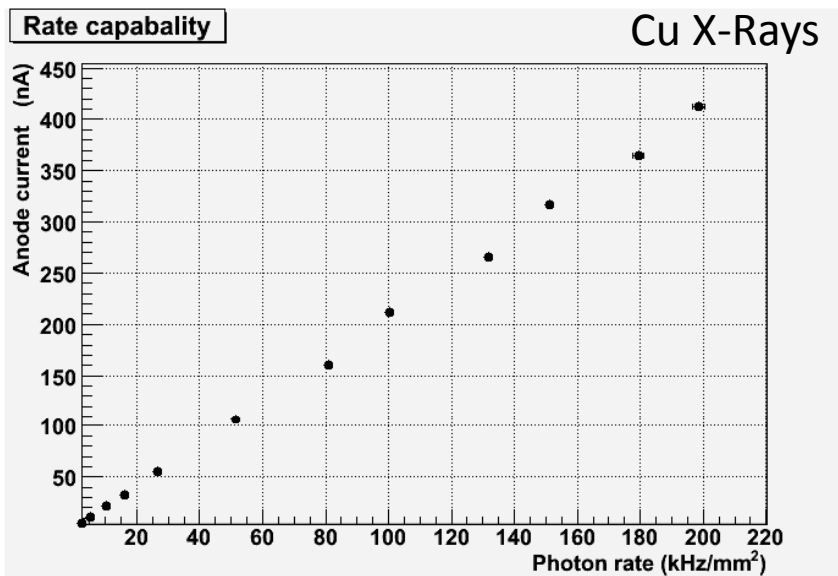
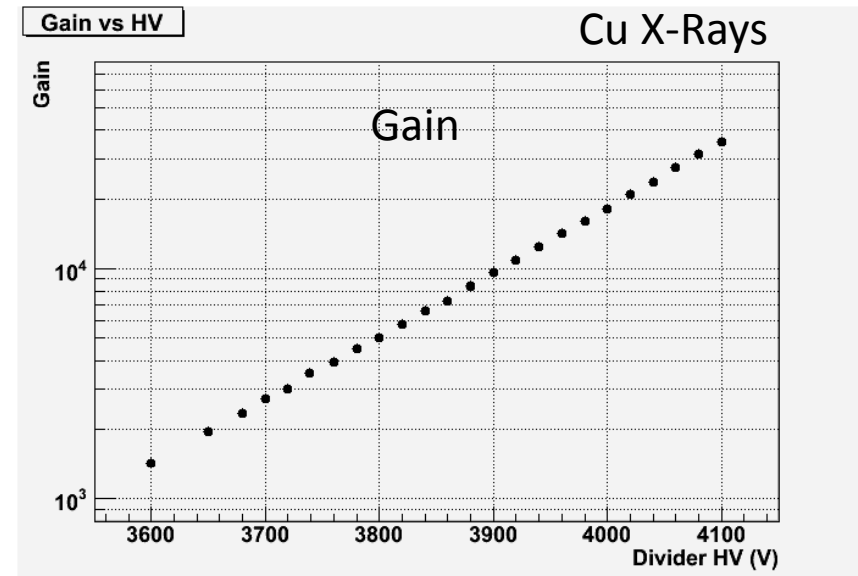
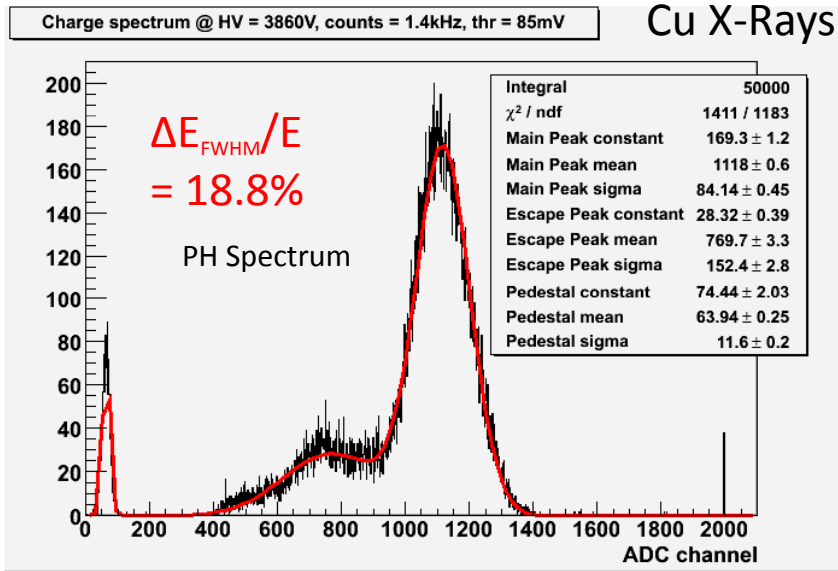
350 μm 400 μm



Cartesian 2D X-Y Readout

C. Altumbas et al, NIM A490(2002)177

Measurements performed so far (before irradiation)



Radiation Hardness tests of Triple GEM detector components

- Materials to be tested:
 - GEM Polyimide (Apical AV Kaneka)
 - Glue (Araldite AY103) + Hardener (HY951)
 - Frames Material (Permaglas)
- Tests to be performed
 - Electric Test
 - Measure **kapton resistivity** before and after gammas irradiation
 - Mechanical Tests: make mechanical tests on components that represent crucial part of detector assembly
 - **Shear Test**
 - **Peeling Test**

We found a very old paper on kapton irradiation.

R.G. Filho et al, "Induced conductivity of Mylar and Kapton irradiated by X-Rays", IEEE Transactions on Electrical Insulation Volume EI-21 No. 3, June 1986

Kapton Samples of 80 mm diameter with thickness varying from 6 to 75 μm were irradiated with W X-Rays for several hours; They saw a variation of the Kapton conductivity

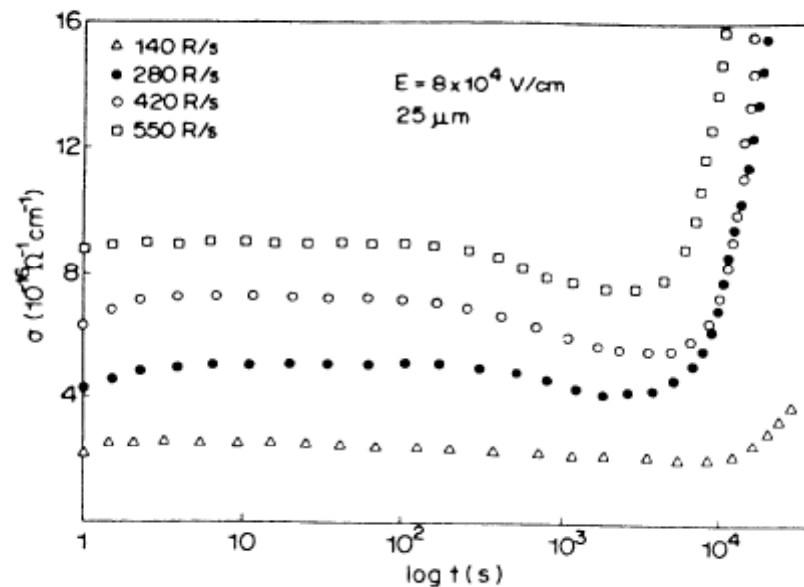
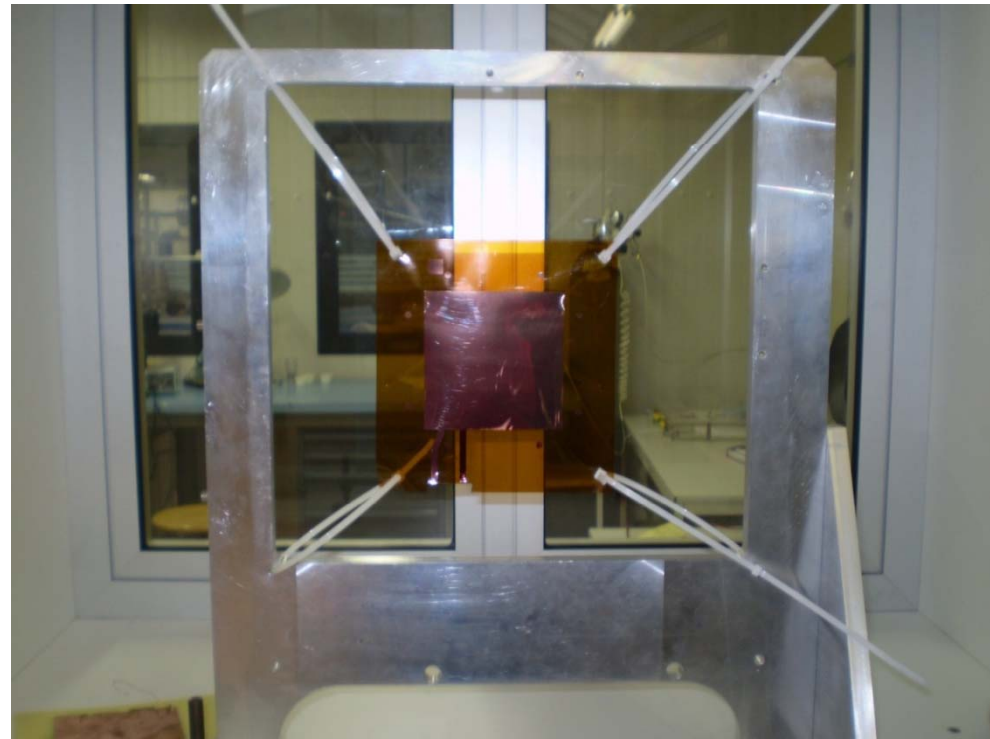


Fig. 14: Kapton: RIC as a function of time for different exposure rates.

First Lab Irradiation Test (prelim. results)

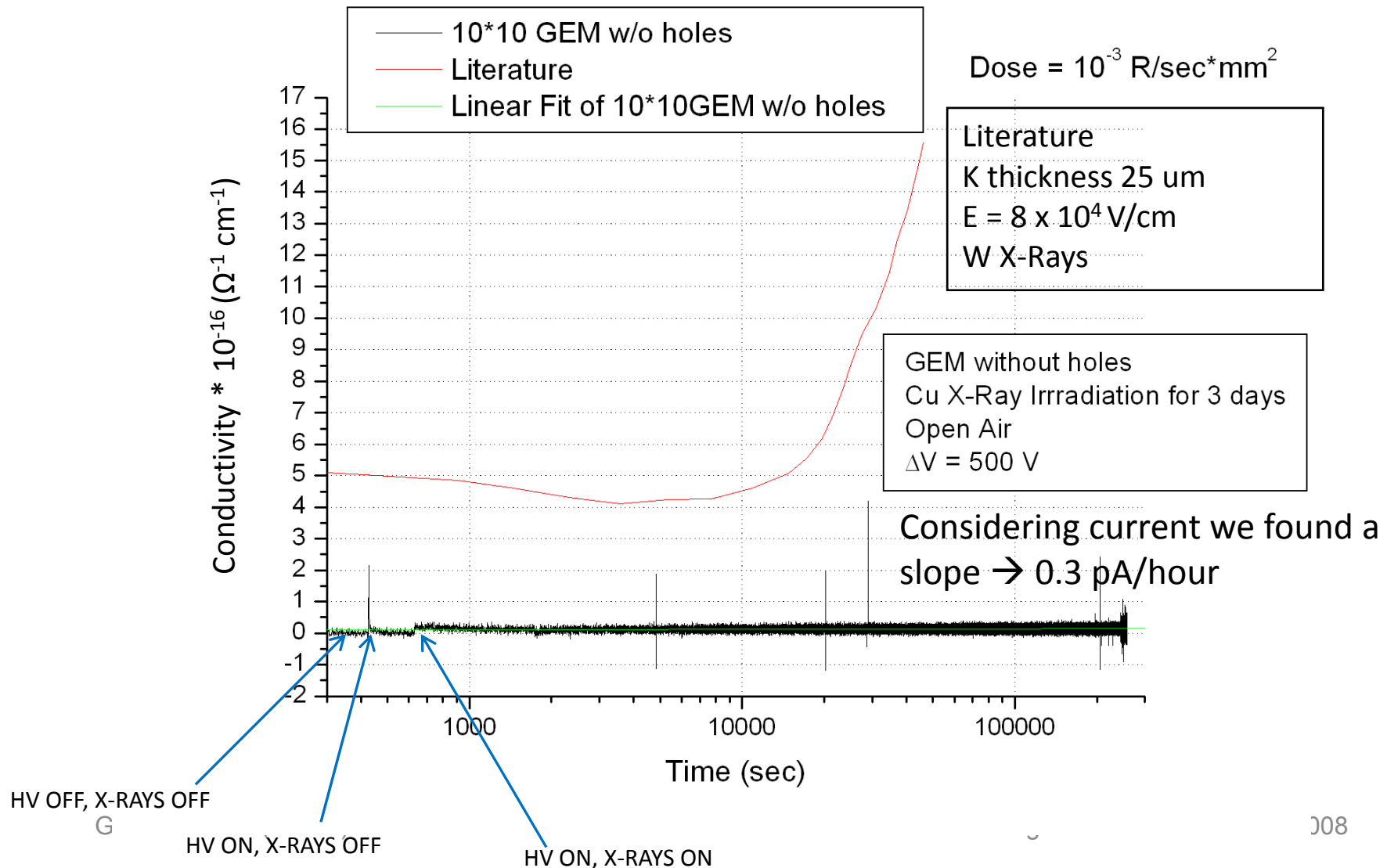
Measurement of Induced Conductivity inside a copper-clad 50 μm thick kapton foil (**GEM w/o holes**)

This copper-clad kapton foil was powered with 500 V and irradiated at very high rate in open air with Cu X-Rays to understand if irradiation will vary its conductivity. Since measurement was performed in open air, air ionisation could be a problem.

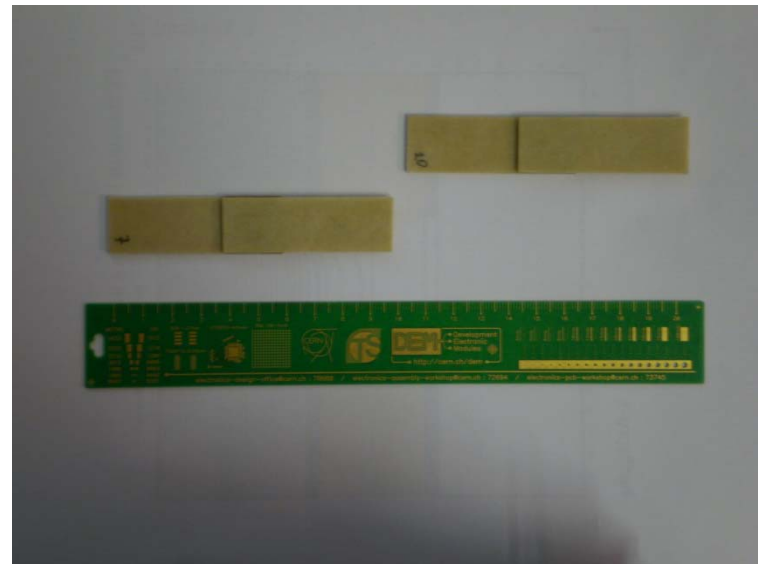
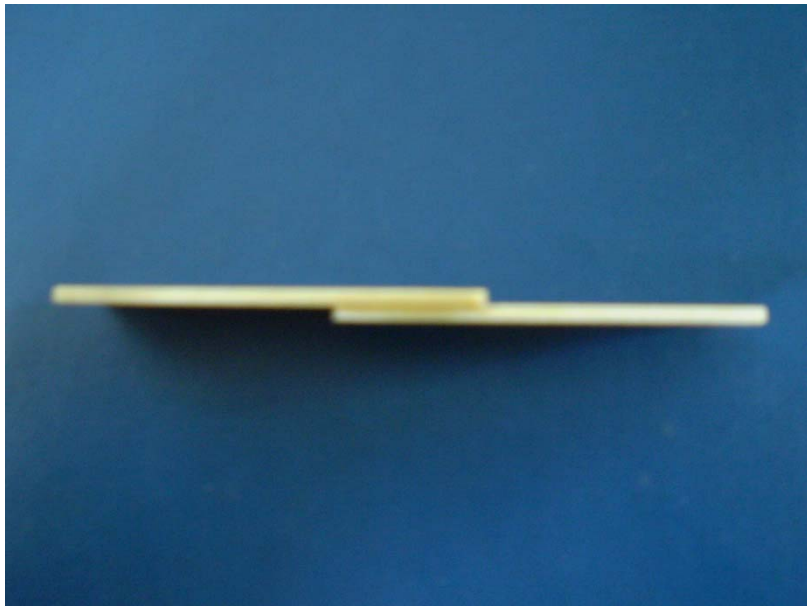
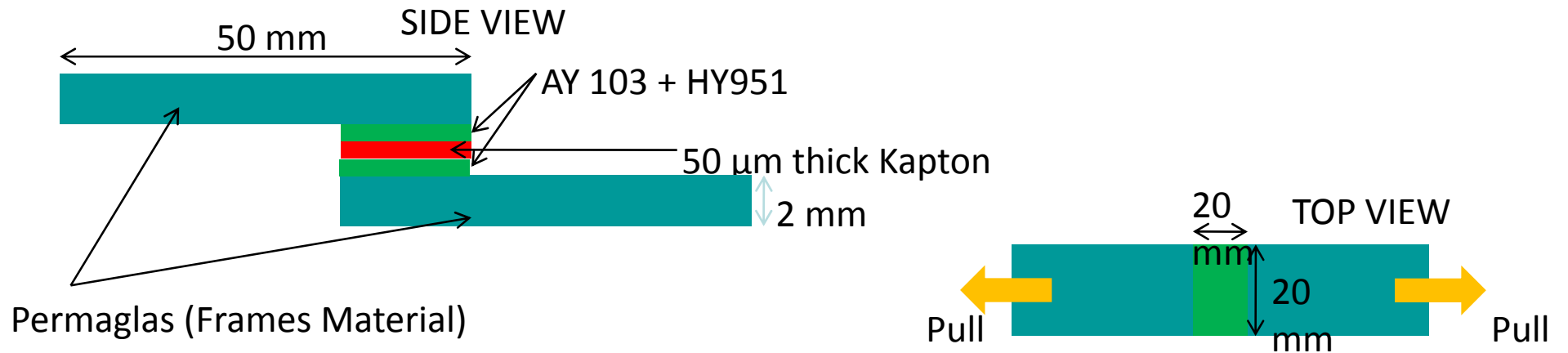


The current flowing from the top to the bottom electrode was monitored during irradiation

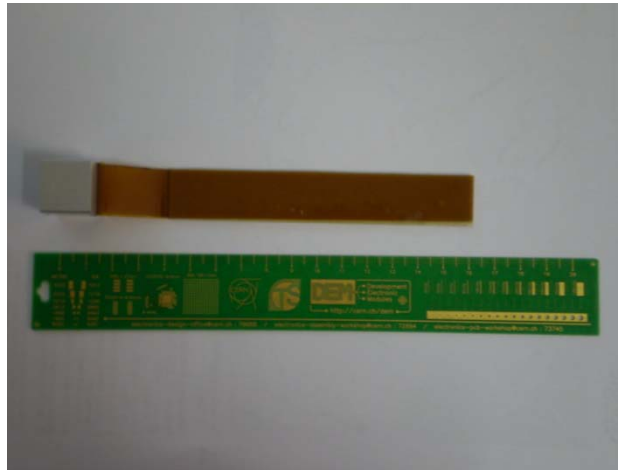
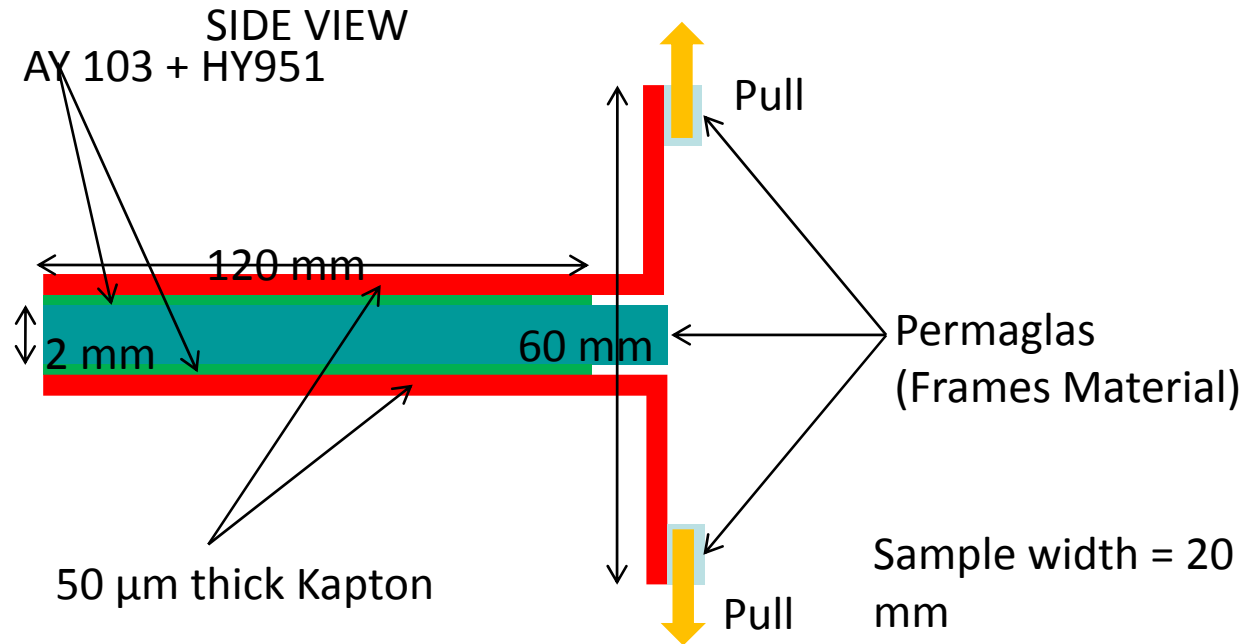
Measurement of Induced Conductivity inside a copper-clad kapton foil (GEM w/o holes)



Shear Test Samples



Peeling Test Samples



Previous studies on Araldite AY103 +HY951

Material: Epoxy structural adhesive
 Type: Araldite AY 103/HY 951 (100/8)
 Supplier: Ciba-Geigy

ID No. M 523

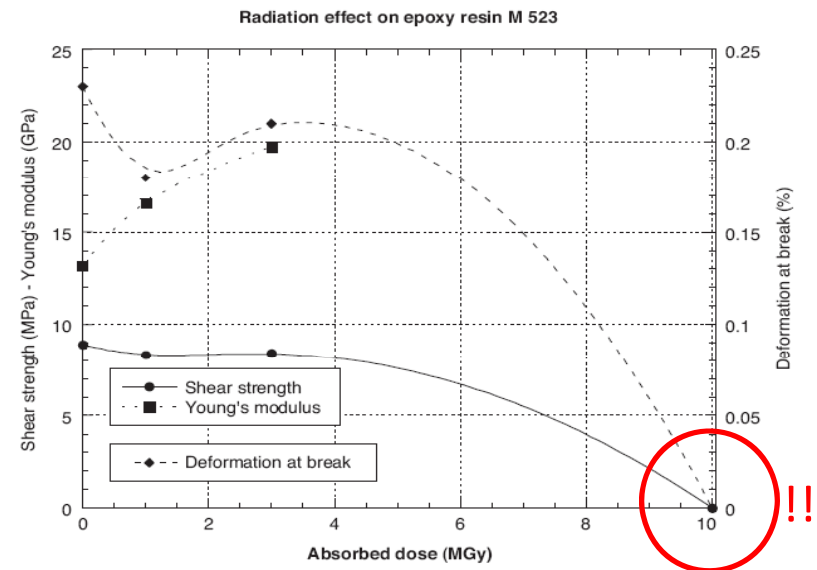
Test method: Shear test with aluminium samples
 Sample geometry: Equivalent to ASTM D 1876-93
 Surface treatment: Sand blasting
 Polymerization temperature: 25°C
 Radiation source: Cobalt 60 and Switched-off reactor

Absorbed dose (MGy)	Dose rate (kGy/h)	Shear strength (MPa)	Deformation at break (%)	Young's modulus (GPa)
0	0	8.9 ± 0.6	0.23 ± 0.03	13.2 ± 6.6
1	4	8.3 ± 0.5	0.18 ± 0.04	16.6 ± 1.1
3	4	8.4 ± 0.3	0.21 ± 0.01	19.7 ± 1.8
10	20	0.0	0.0	-

Critical property = deformation at break
 Radiation index (RI) ~ 6.7 at a mean dose rate of 4 kGy/h

Studies made at CERN some years ago on the same glue used in Triple GEM detectors assembly

Compilation of radiation damage test data, 4. / Guarino, Francesco et al. CERN-2001-006. - Geneva : CERN, 2001. - 131 p.



Present Situation

- We are performing the tests before irradiation **but now we need to find a ^{60}Co irradiation facility!!!!**

ANY SUGGESTIONS??????

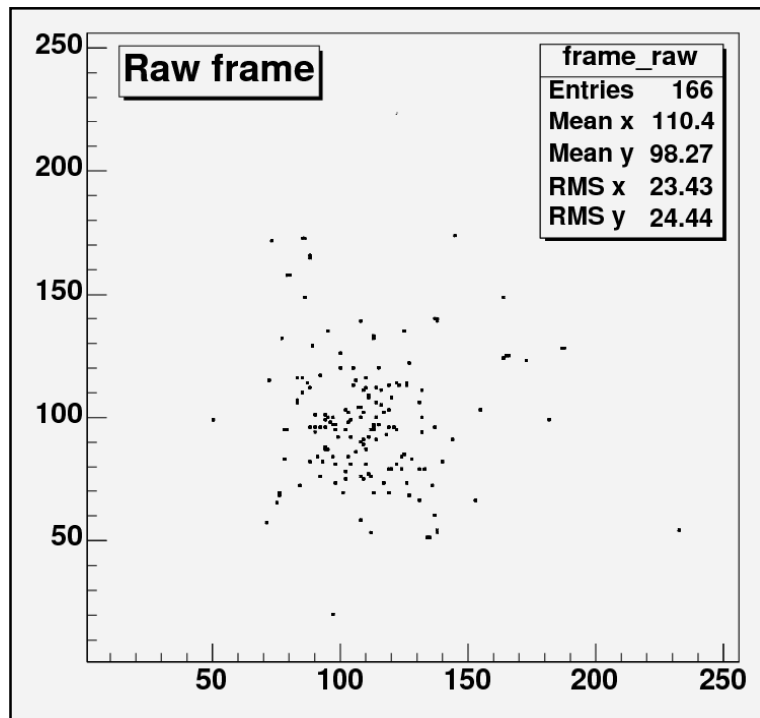
Is anybody interested in irradiating other detectors or components ???

Digital primary electron counting:
W, Fano Factor, Polya vs
Exponential

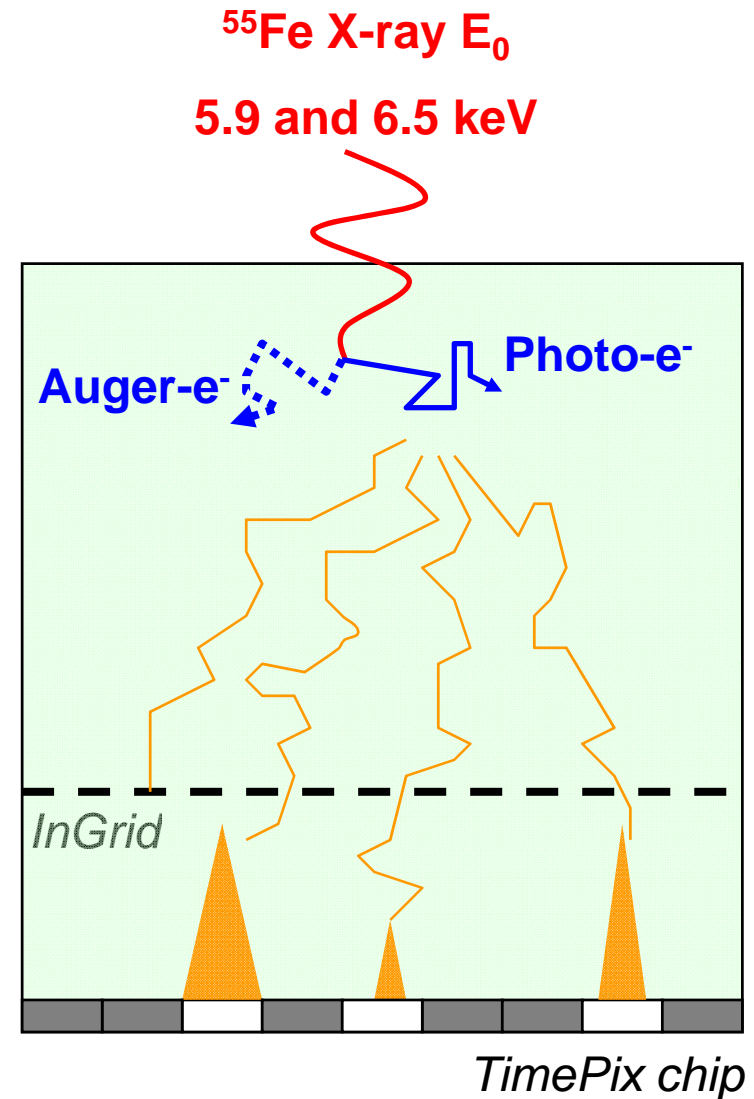
M. Chefdeville, NIKHEF, Amsterdam
RD51, Paris, 13-15 October 2008

^{55}Fe quanta conversions seen by GridPix

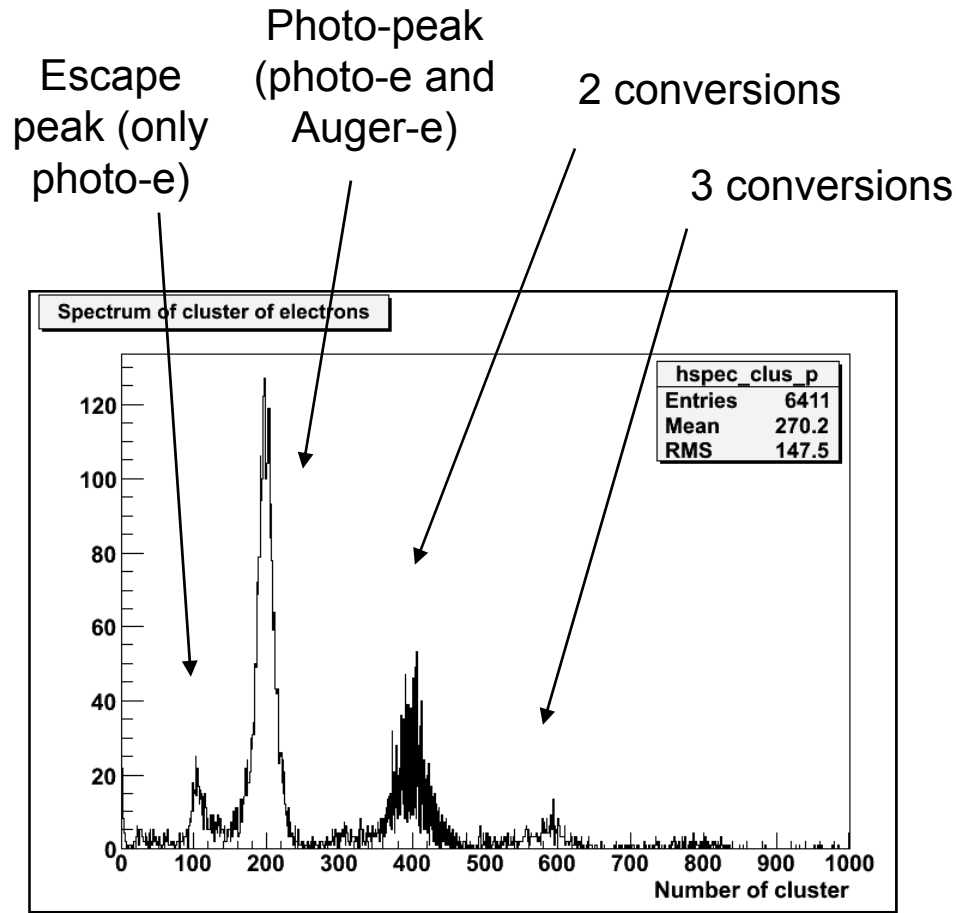
After large drift distance, primary e^- separate and can be counted



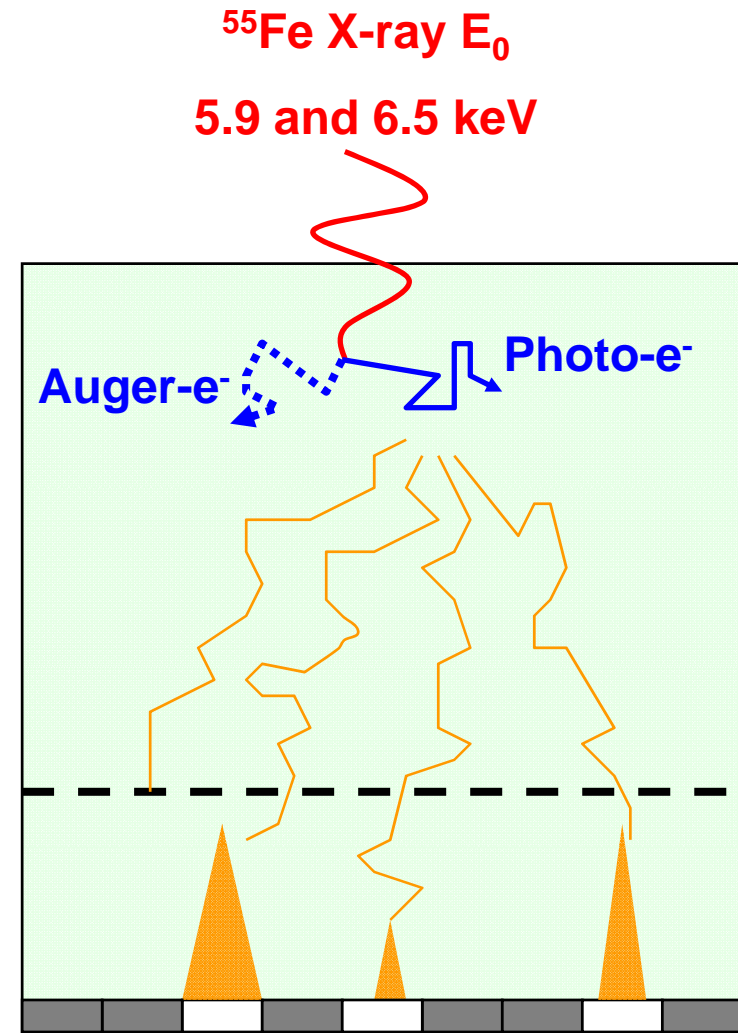
Gas mixture: Ar/iso 95/5



^{55}Fe quanta conversions seen by GridPix



Raw spectrum



Look at the escape peak only (smallest number of primary electrons)

Measurements of W and F

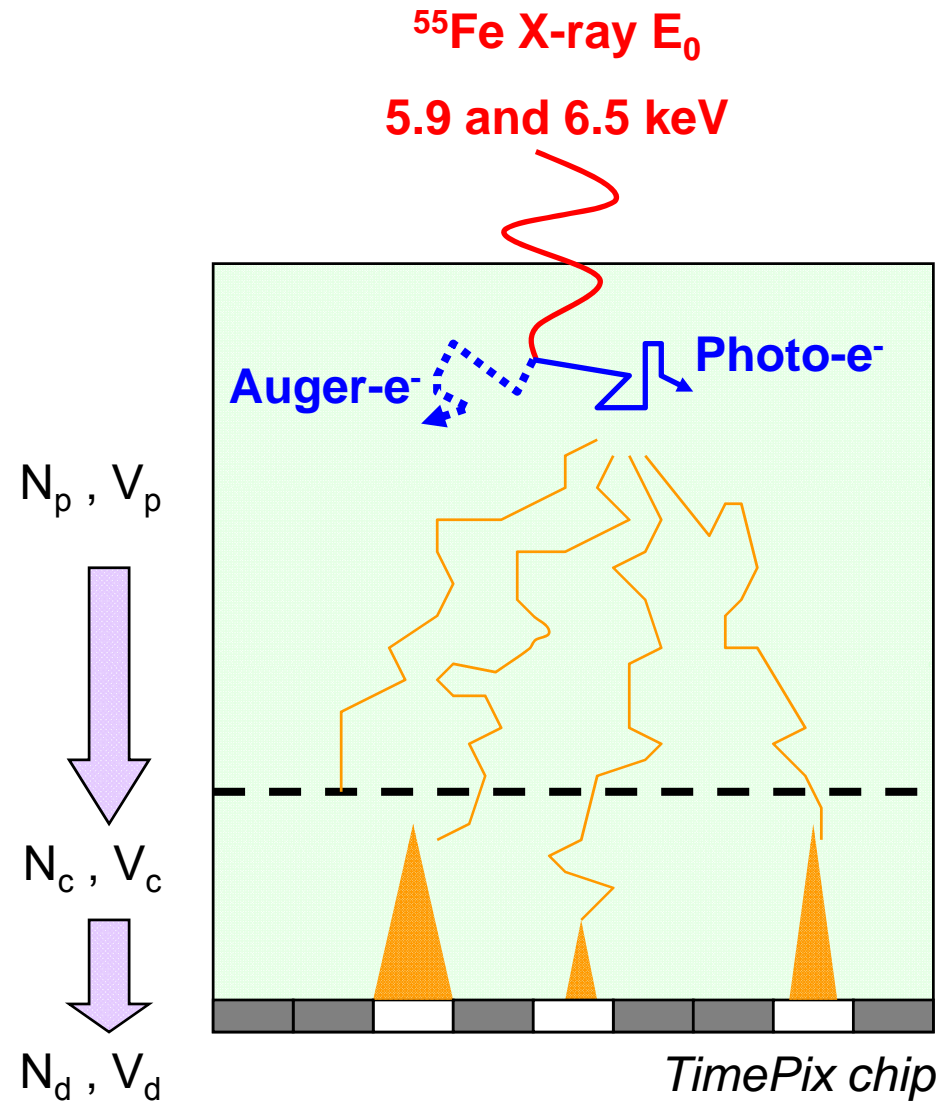
What is measured is the mean and variance of the number of detected electrons (N_d , V_d)

Correction for limited collection and detection efficiencies yield N_p and V_p

$$W = E_0 / N_p$$

$$F = V_p / N_p$$

Collection and detection eff. should be known



Detection efficiency

$$\kappa = \int_t^\infty p(g).dg$$

Exponential fluctuations:

$$\kappa(g) = \exp(-t/\langle g \rangle)$$

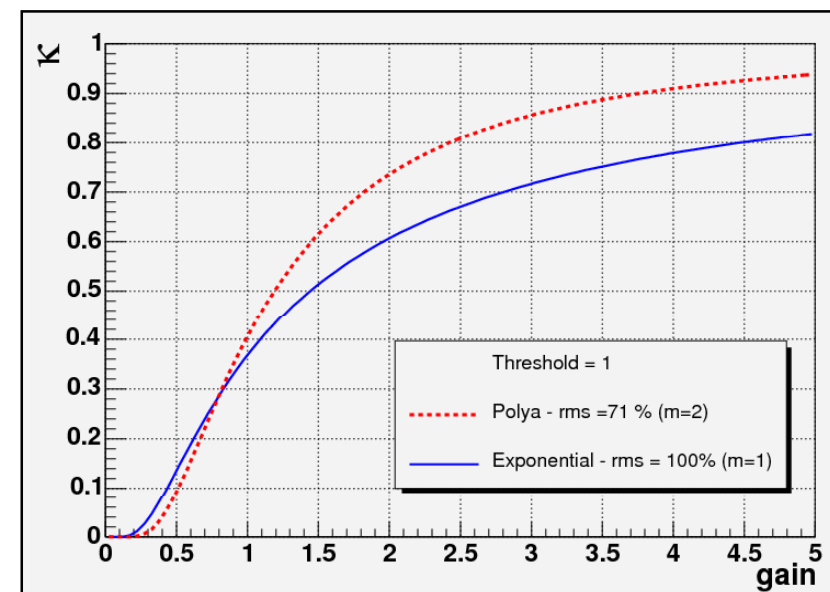
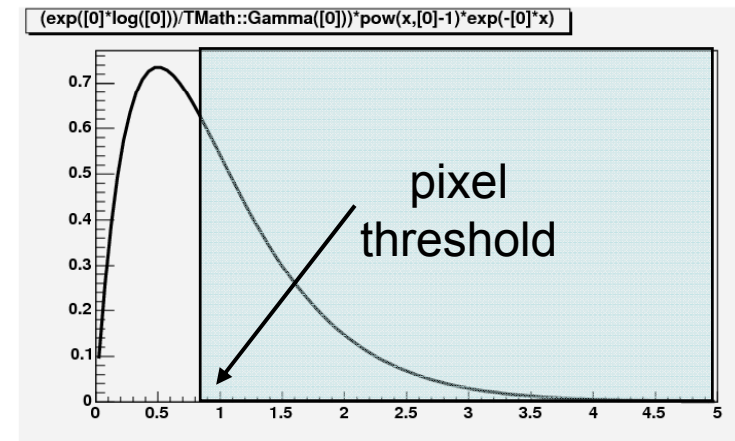
Polya-like fluctuations:

parameter $m=1/b \sim 2$

with \sqrt{b} the relative rms

$$\kappa(2,g) = (1+2.t/\langle g \rangle) \cdot \exp(-2.t/\langle g \rangle)$$

Detection efficiency will be determined by fitting $\kappa(g)$ to (N_d, V_{grid}) data points

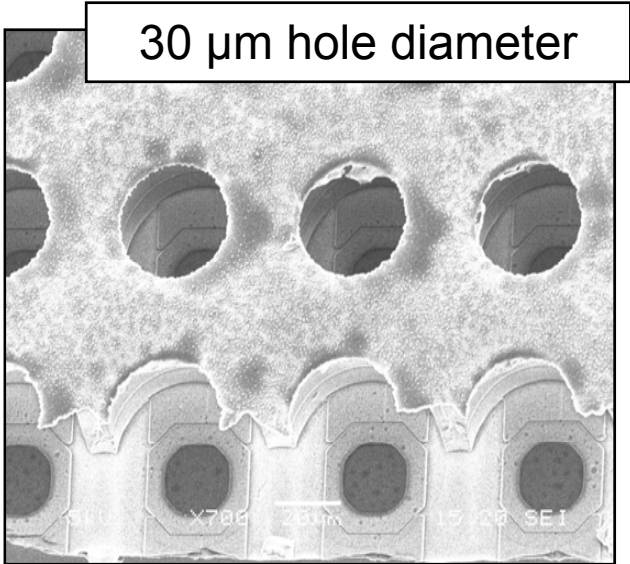
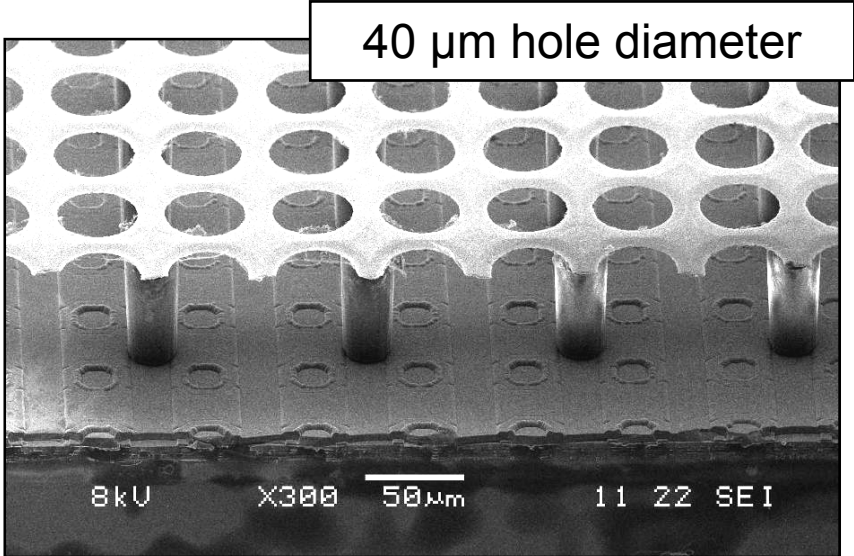
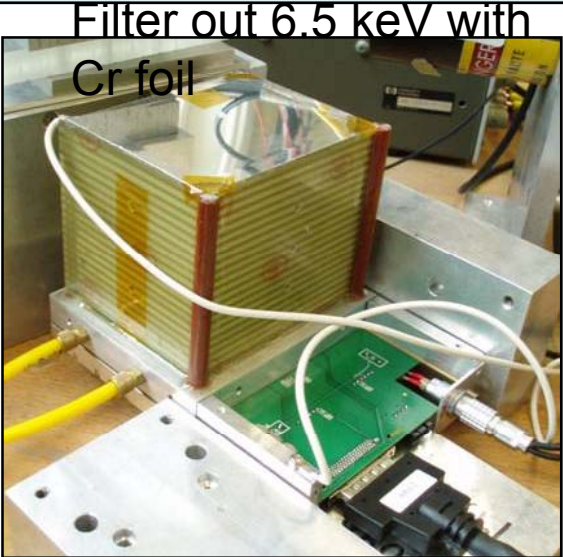


Detectors

Two measurement periods

Timepix chip # 1:
Standard InGrid
Low event

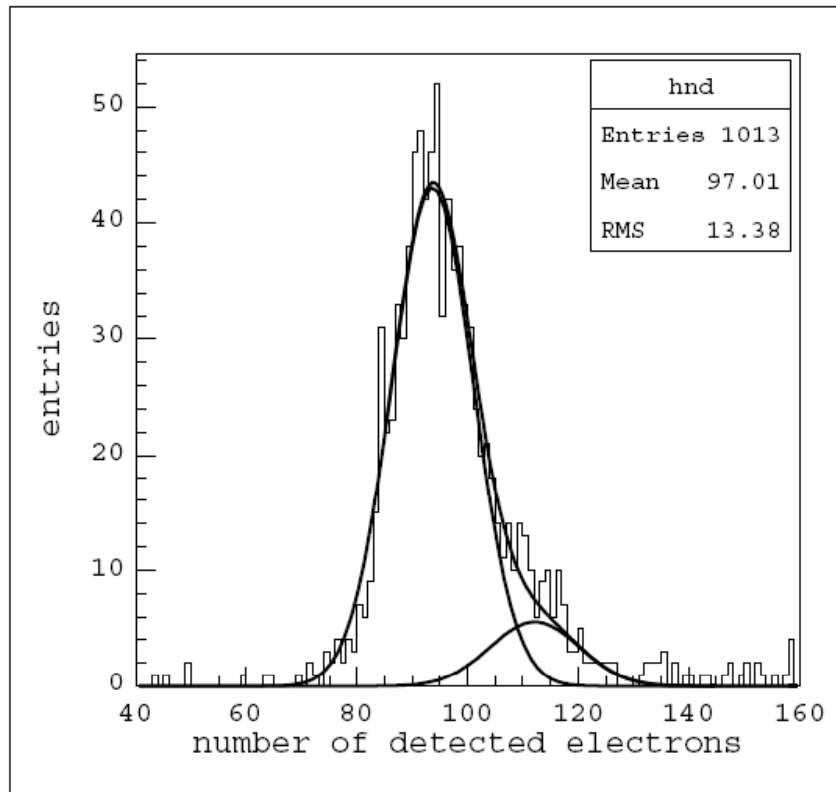
Timepix chip #2 :
Increased event
statistics
New GEMGrid structure



Chamber geometry:
10 cm field cage
Guard electrode surrounding the chip
(inside chamber)

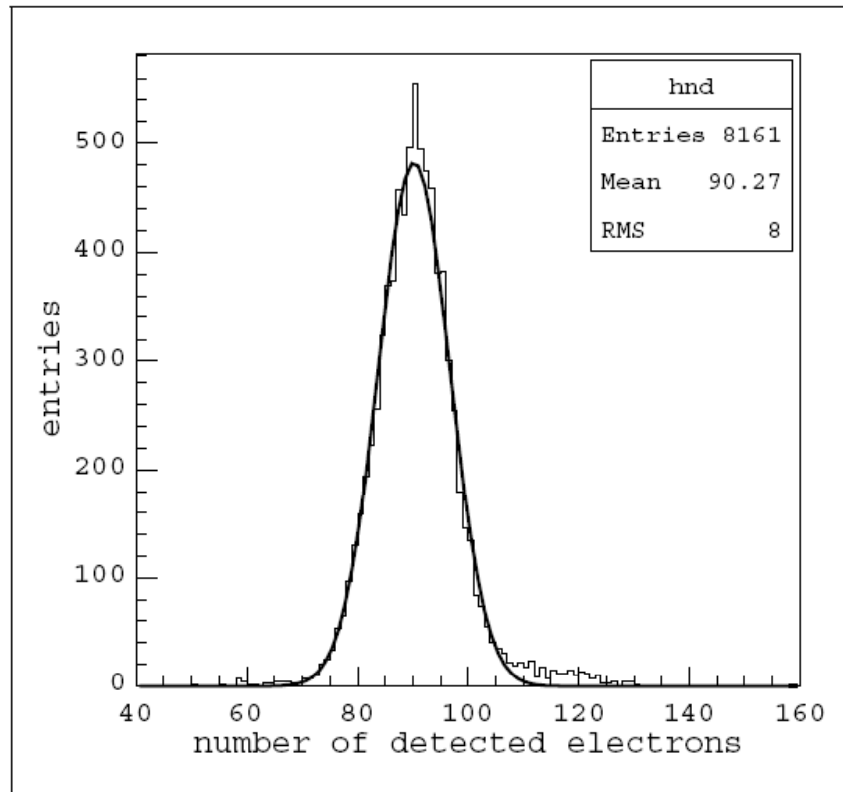
Measured spectra at -330 V

- Timepix #1



5.9 and 6.5 keV escape events
(event ratio ~ 7:1)

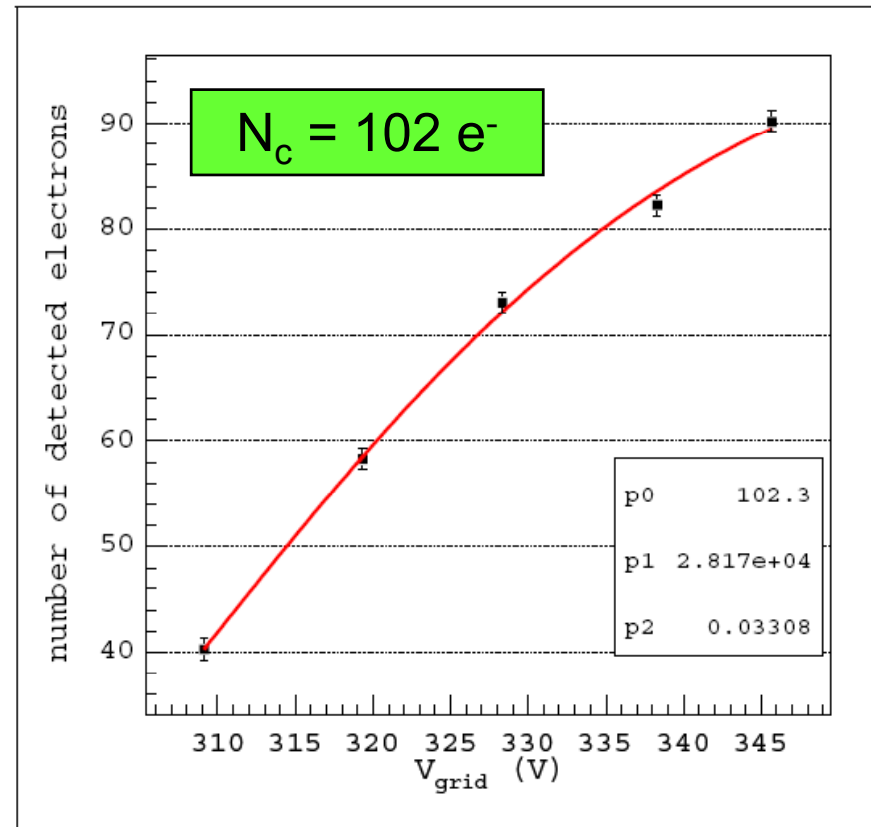
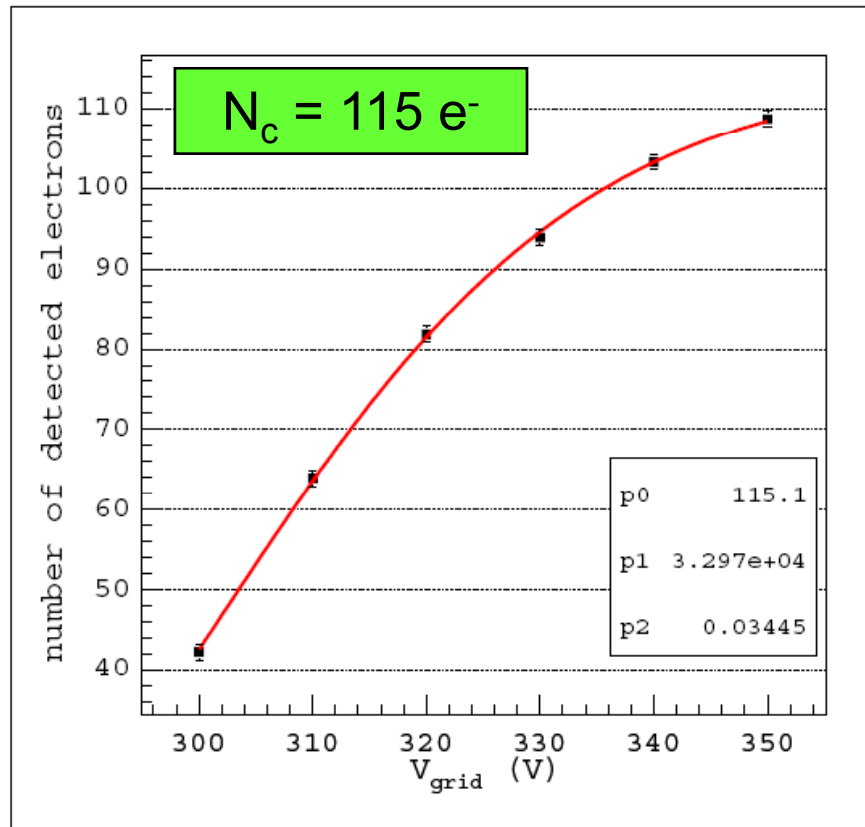
- Timepix #2



5.9 and 6.5 keV escape events
(event ratio ~ 50:1)

Peak position and grid voltage

Asymptotic value of N_d gives the number of collected electrons N_c
Polya fit works very well where exponential one (not shown) fails!

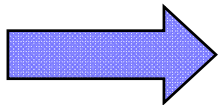


- Compatible with the smaller hole diameter of InGrid #2
- Contribution from collection efficiency to peak width now known

W and F in Ar/iso 95/5 at 2.9 keV

Assume full collection efficiency of detector #1

$$N_p = N_c = 115 \pm 2 e^-$$



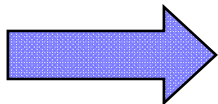
$$W = 25.2 \pm 0.5 eV$$

Extrapolation to 5.9 keV photo-peak straightforward

$$N_p = 230 \pm 4 e^-$$

Peak width measured with detector #2 corrected for detection and collection eff. (87 %)

$$\text{RMS}(N_p) \sim 4.3 \%$$



$$F = 0.21 \pm 0.06$$

Compatible with literature

$$W = 25.0 \pm 0.6 eV$$

$$F = 0.250 \pm 0.010$$

Ar/iso 20/80 – 1253 eV X-rays from Pansky. *et al.*

J. Appl. Phys. **79** (1996) 8892

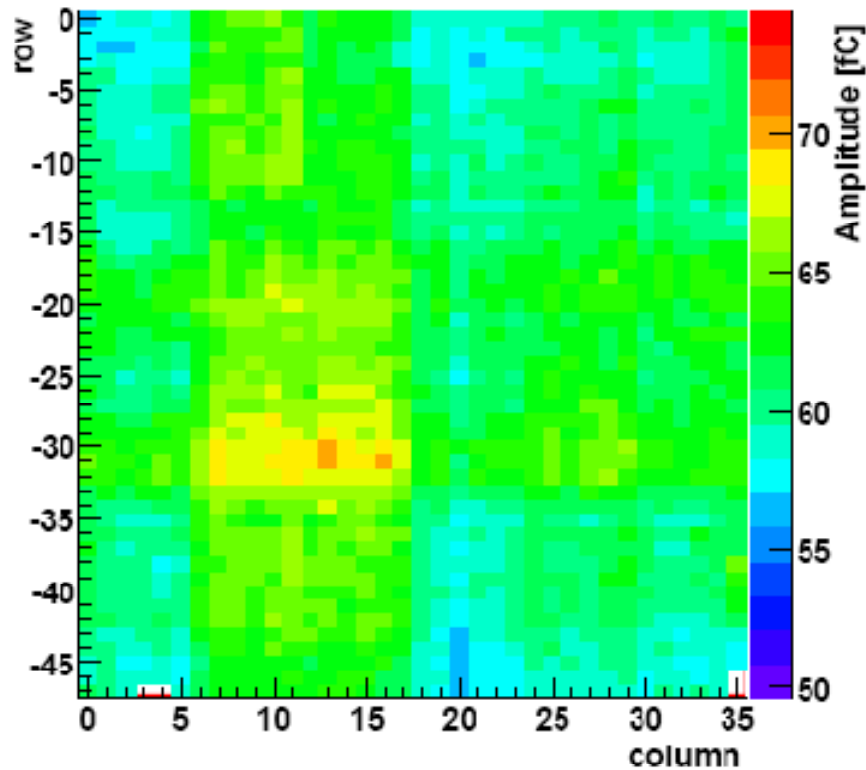
T2K Test Bench results on uniformity and reproducibility of Micromegas production

A. Ferrero*

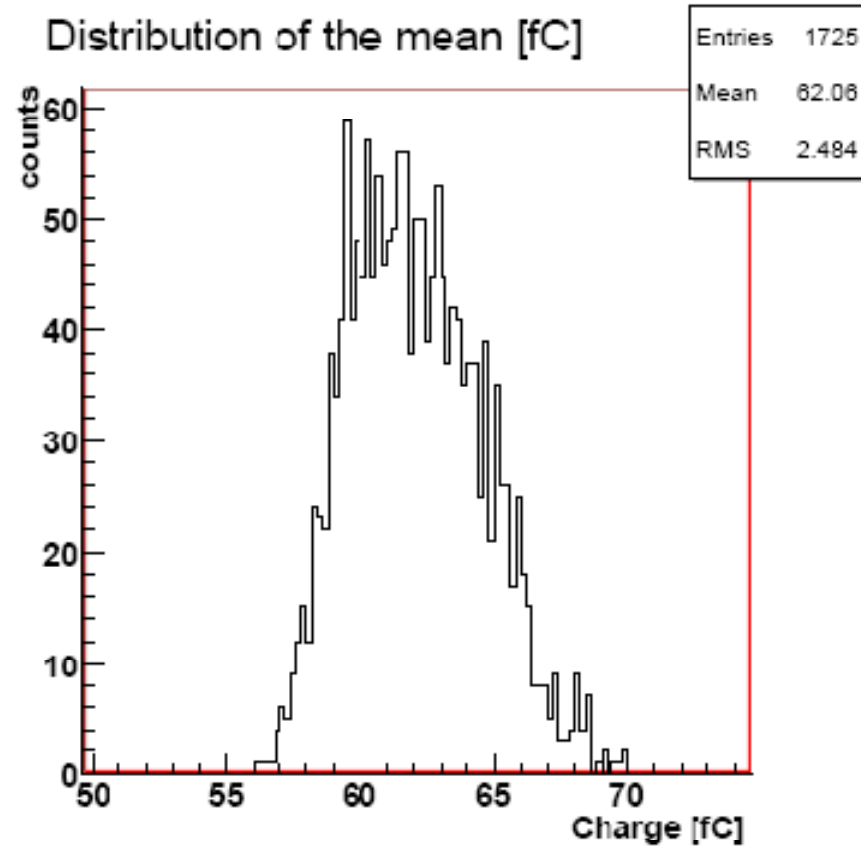
for TRIUMF, University of British Columbia, University of Victoria,
IRFU-CEA/Saclay, RWTH Aachen University, INFN Italy, Barcelona
University, Valencia University and University of Geneva*

RD51 Collaboration Meeting, October 14 2008

Map of the gain (mean value)



Distribution of the mean [fC]



- Measurements performed at the nominal mesh voltage of -350V
- Each bin in the 2D map represents one pad (36×48 matrix)
- Signal amplitude dispersion: $\sim 4\%$ RMS

Scintillation Readout From THGEMs operating in xenon

Joaquim M.F. dos Santos



University of Coimbra;



University of Aveiro



Weizmann Institute of Sciences

Universidad Autónoma de Barcelona/ Universidad Politécnica de Valencia

2nd RD51 collaboration meeting

13-15 Oct. 2008, Paris

Recent Relevant Applications of Optical TPCs

Double Beta decay Experiments

NEXT – Neutrino Xenon TPC

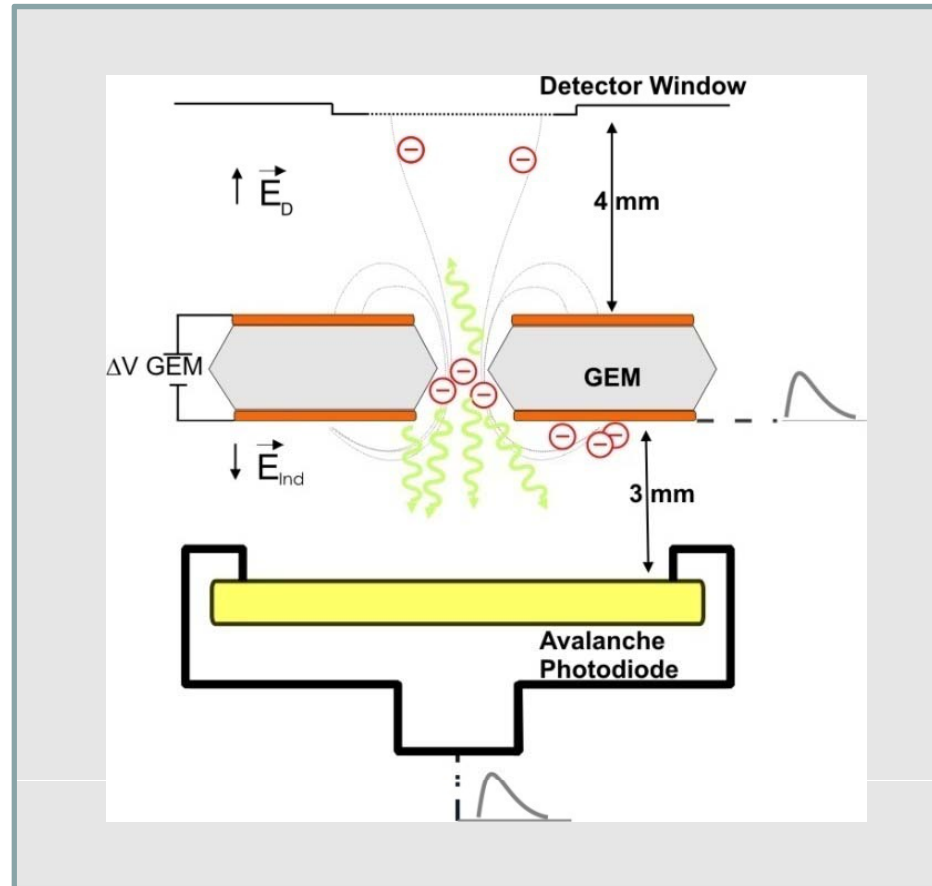
Dark Matter search

XENON, LUX, ZEPELIN, WARP
experiments

- Secondary scintillation
amplification, for higher sensitivity, with PMT/LAAPD readout
 - Double mesh, uniform field scintillation gap
e.g. secondary scintillation yield of
466 photons/e⁻/cm @ 4.1 kV/cm/bar
(C.M.B. Monteiro et al., J. Inst. 2 P05001)
 - Scintillation in hole-type microstructures, e.g. THGEMs



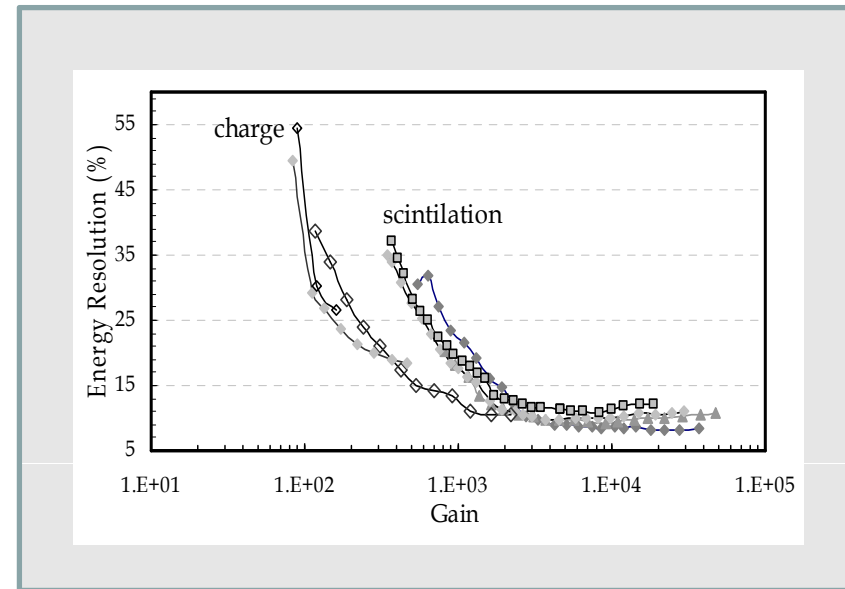
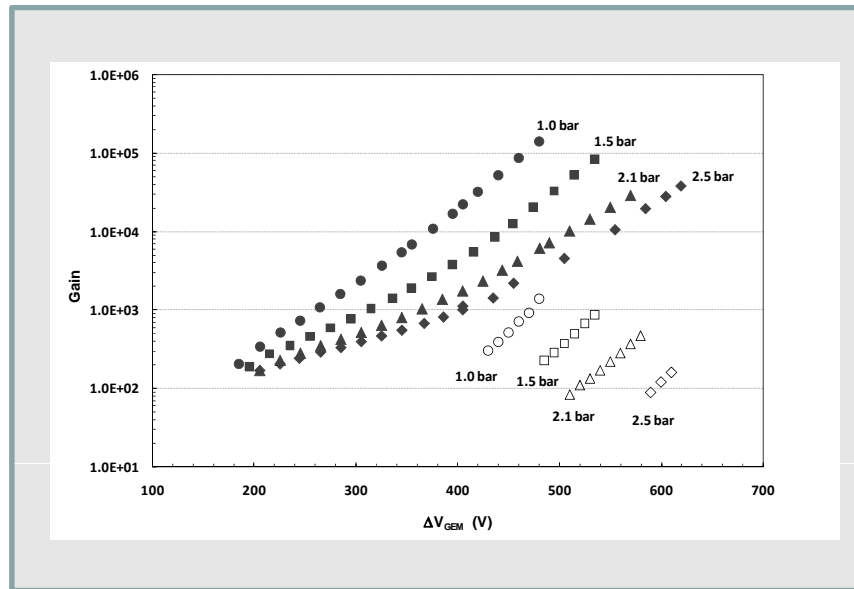
MPGD scintillation vs. charge readout



A.S. Conceição, et al., J. Inst. 2 P09010



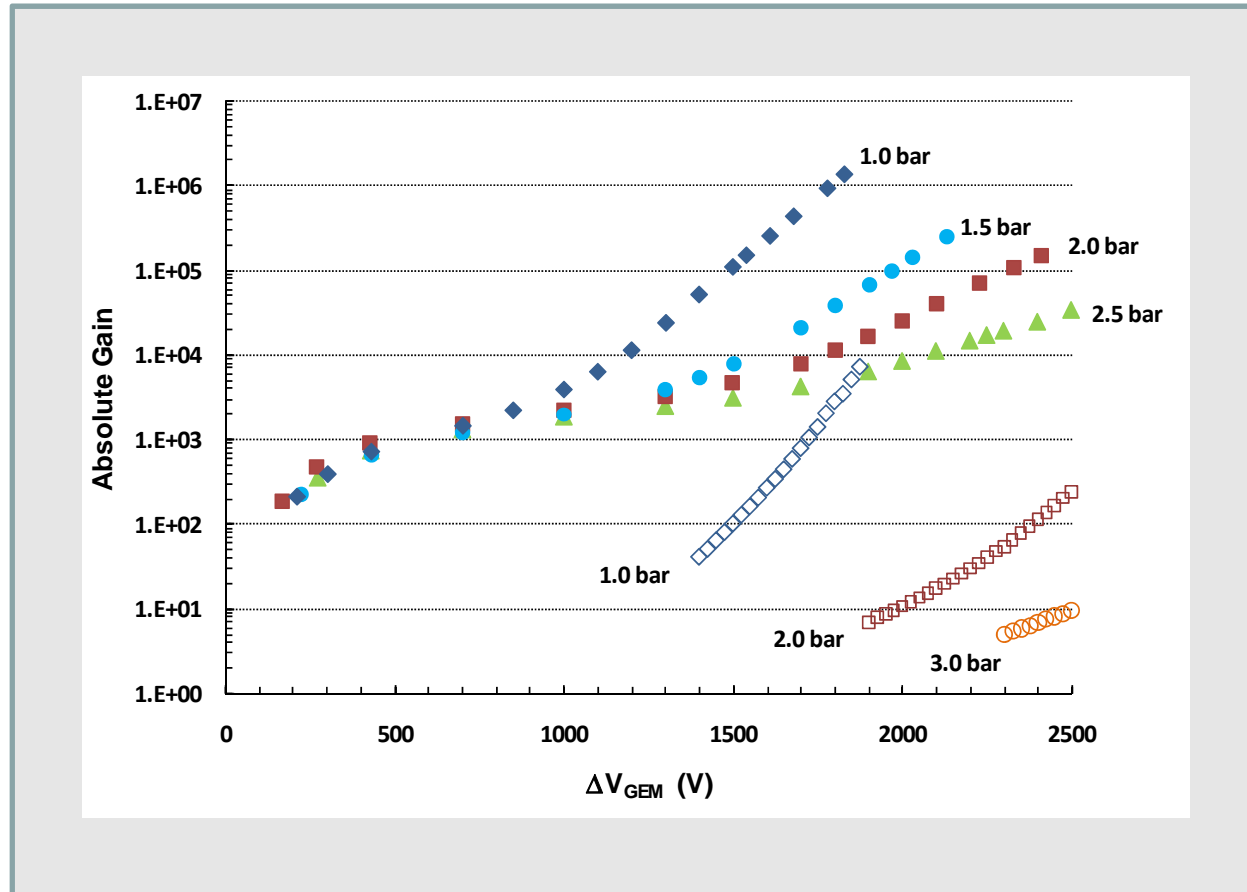
GEM scintillation vs. charge readout



LAAPD gain ~130 - 150



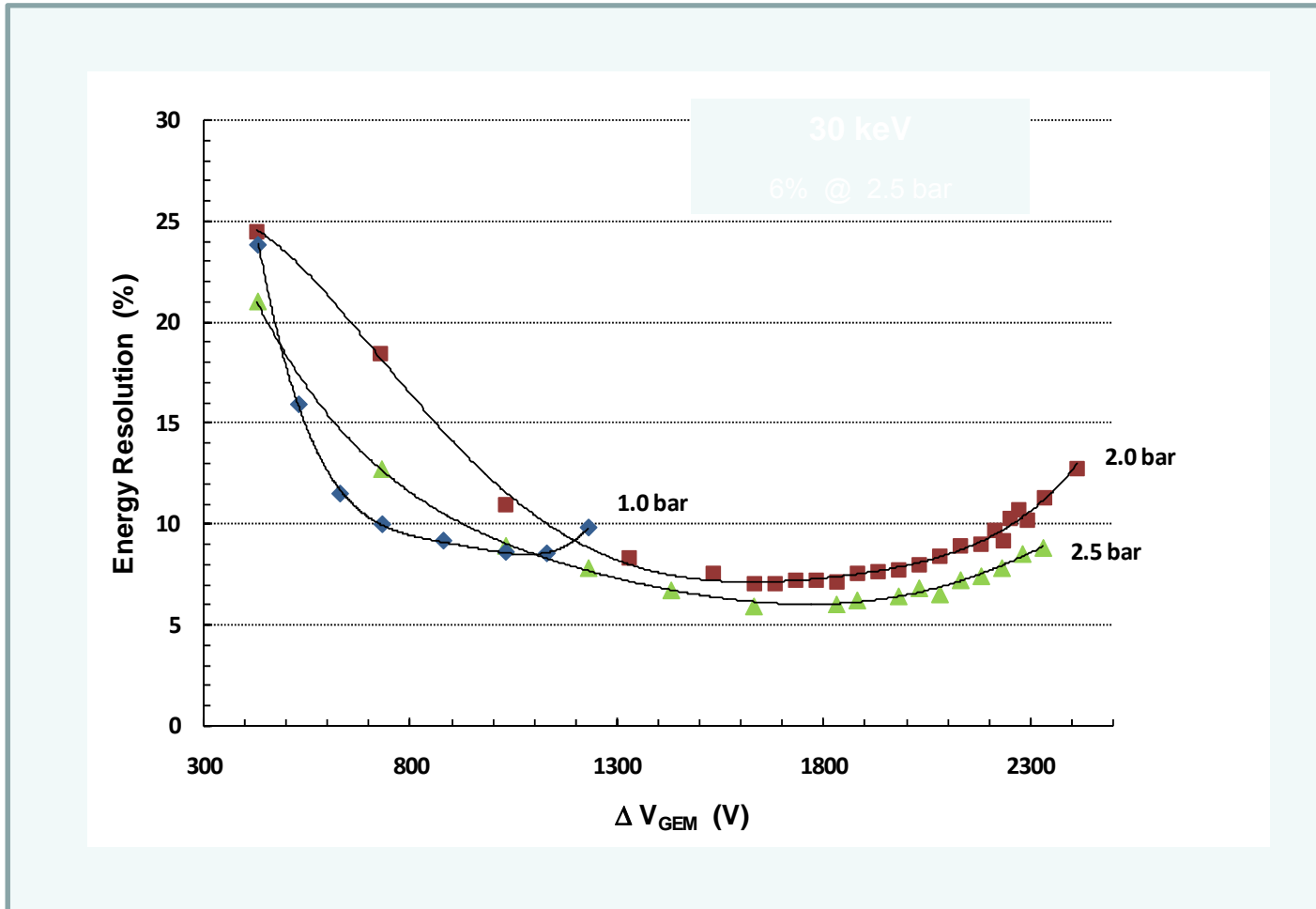
THGEM scintillation vs. charge readout



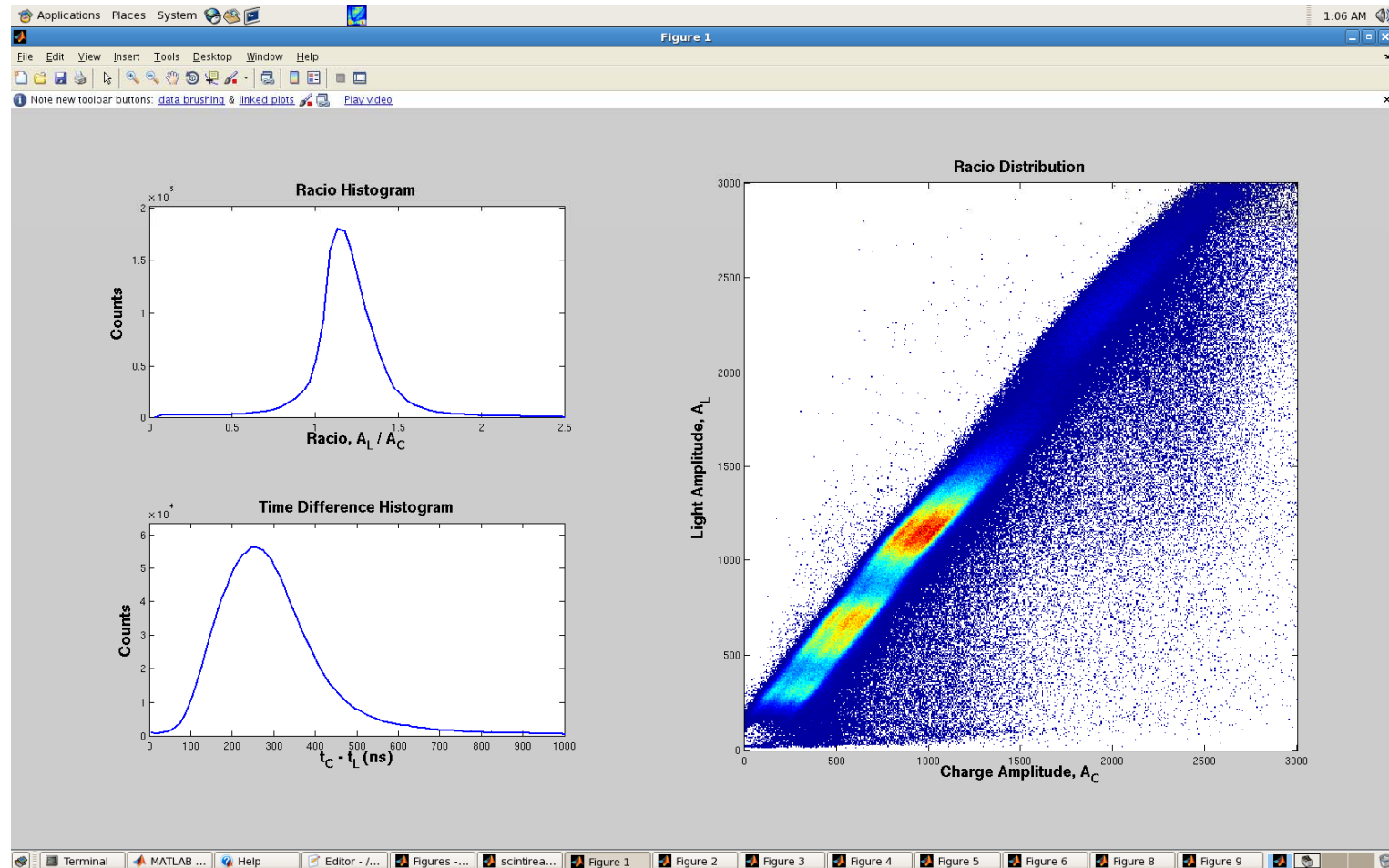
LAAPD gain ~130 - 150



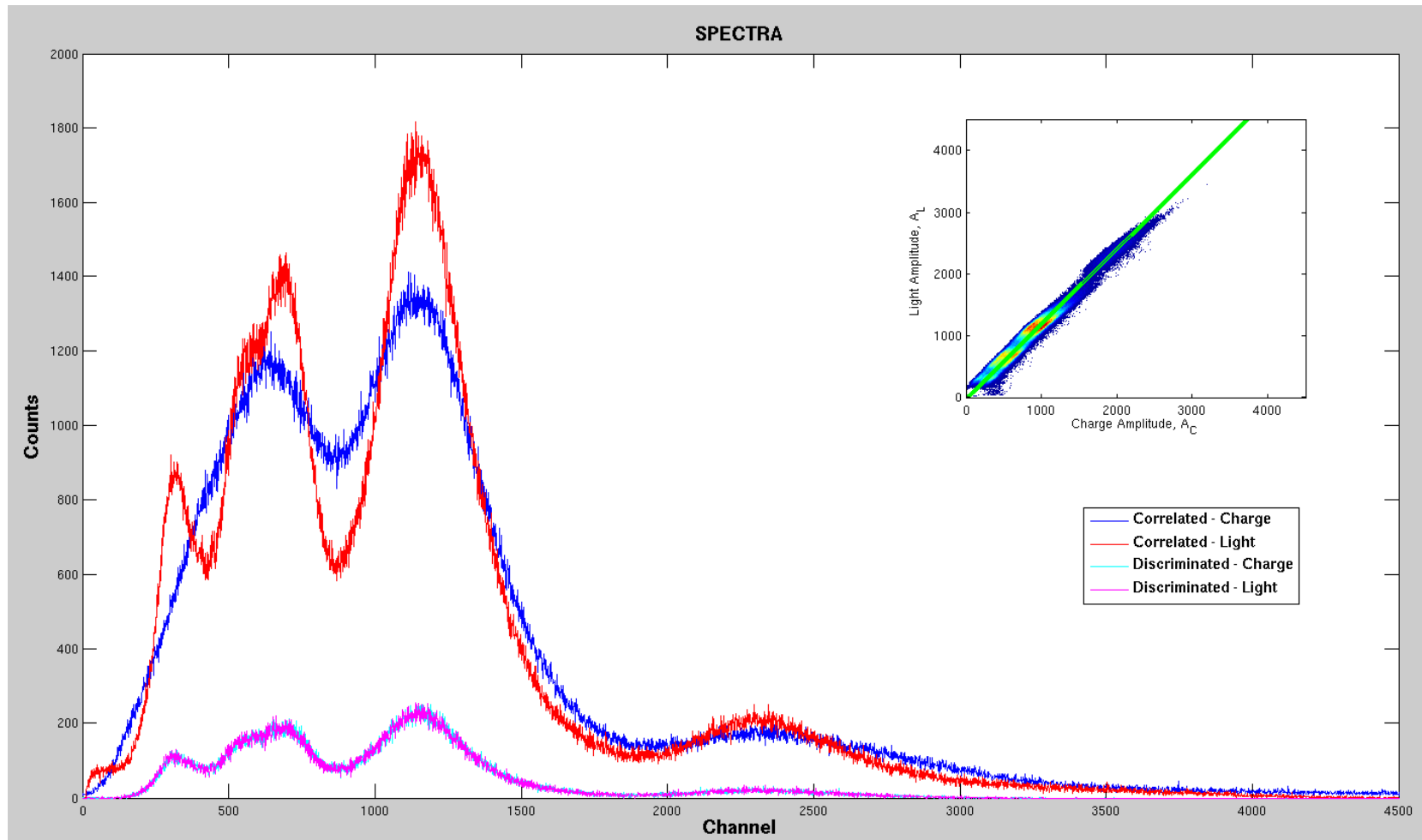
THGEM scintillation – Energy Resolution



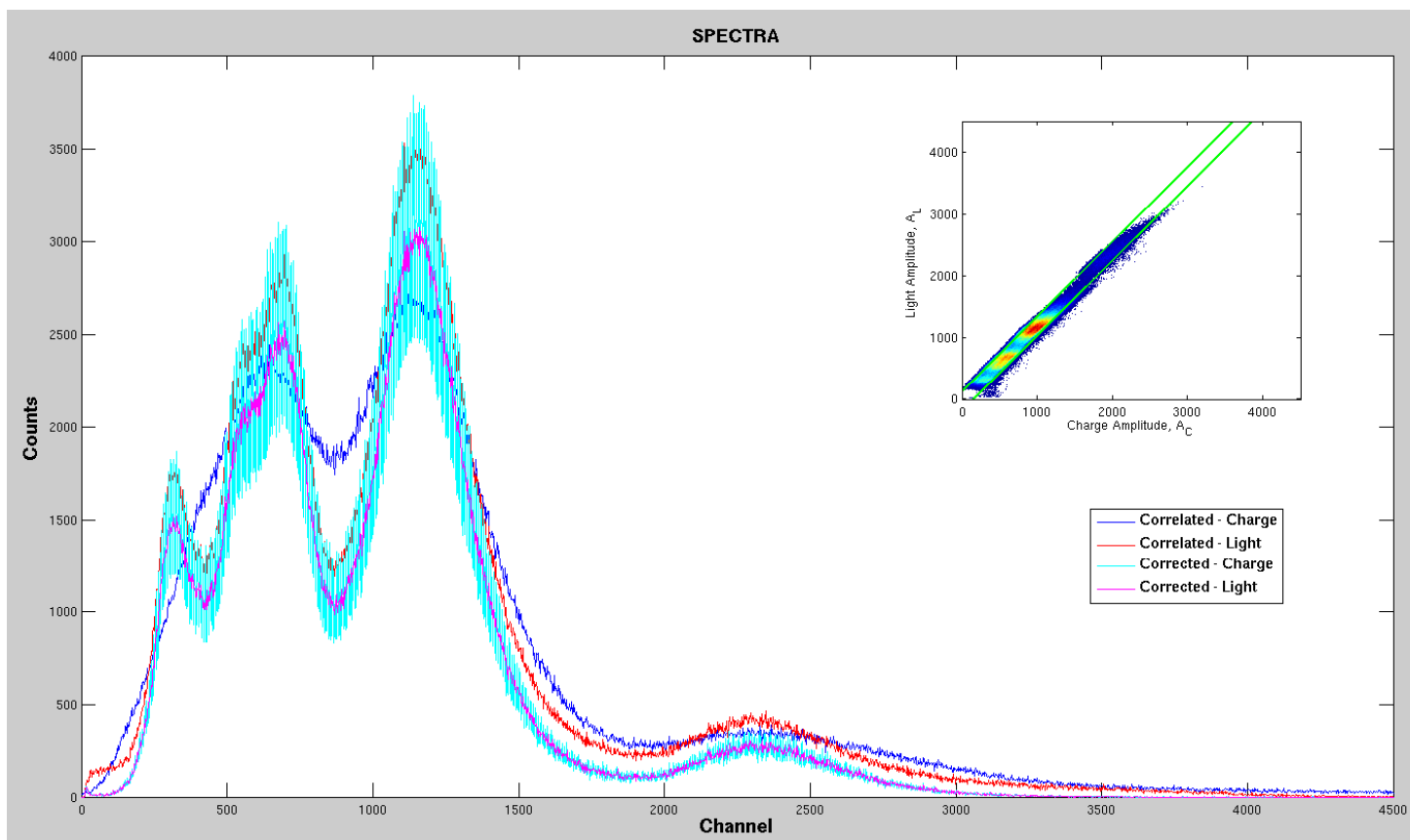
Scintillation and charge pulses correlation



Scintillation and charge correlated spectra



Scintillation and charge corrected spectra





Test Beam Measurements for a TGEM Based Trigger Detector



ELTE, MTA KFKI RMKI Collaboration
(Budapest, Hungary):

G. Bencze, L. Boldizsár, G. Hamar,
L. Kovács, P. Lévai, D. Varga

RD51 Collaboration Meeting, 13-15.10.2008., Paris